Overview

## **HP Z6 G4 Workstation**



## Front view

- 1. Integrated Front Handle
- 2. Front I/O module options
  - Premium (optional, shown here): power button, 2 USB 3.1 G1 Type-A, 2 USB 3.1 G2 Type-C<sup>™</sup> (Left-most Type A port has charging capability), Headset/Mic, Media Card Reader (optional).
  - Standard: power button, 4 USB 3.1 G1 Type-A (left-most Type A port has charging capability), Headset/Mic, Media Card Reader (optional).
- 3. 2 x 5.25" external bays
- 4. 1 Slim ODD bay

## Overview



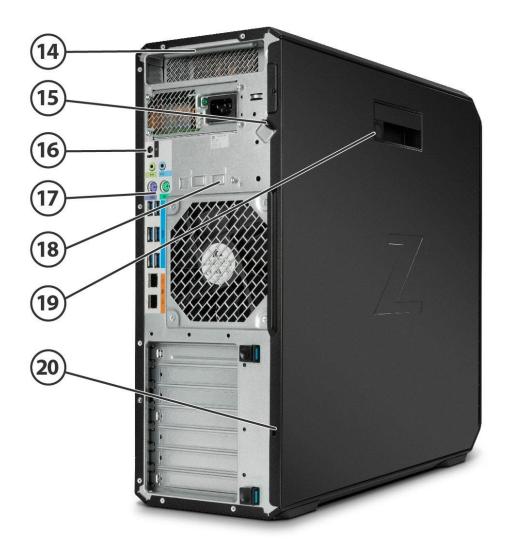
## **Internal view**

- 5. Power supply: 1000W 90% efficient with 2 graphics power adapters
- 6. 6 DIMM slots: DDR4-2666 Registered RAM
- 7. Intel® Xeon® processor Scalable family
- 8. 2<sup>nd</sup> CPU & memory riser connector: adds 2<sup>nd</sup> CPU socket and (6) DIMM slots
- 9. PCIe slots: 2 PCIe G3 x16, 3 PCIe G3 x4, 1 PCIe G3 x8

- 10. 6 x 6Gb/s SATA ports
- 11. 2 PCle G3 x4 M.2 for SSDs
- 12. 2 x 2.5"/3.5" internal drive bays
- 13. 2 x 5.25" external drive bays



## Overview



- 14. Rear handle
- 15. Padlock loop
- 16. Rear power button
- 17. Rear I/O (top to bottom): audio in/out, keyboard/mouse PS/2, 6 USB 3.1 G1 Type-A, 2 x 1GbE LAN ports

## **Rear view**

- 18. HP Dual Port 10GBase-T NIC module slot (optional)
- 19. Side panel barrel keylock (optional)
- 20. Kensington lock slot

## Overview

## **Overview**

Form Factor
Operating Systems

## Minitower Preinstalled:

- Windows 10 Pro 64 for Workstations
- Windows 10 Downgrade to Windows 7
- HP Linux-ready (minimal OS ready for customer OS installation)
- Red Hat® Enterprise Linux® Desktop Workstation (Paper license with 1 year support; no preinstalled OS)

#### Supported:

- Windows 7 Professional 64-bit (downgrade media available by request from HP Support)\*
- Red Hat Enterprise Linux Desktop 7.4
- SUSE Linux Enterprise Desktop 12 SP3
- Ubuntu 16.04 LTS

**Notes**: For detailed Linux® OS/hardware support information, see: http://www.hp.com/support/linux\_hardware\_matrix

\*Windows 10 is preinstalled. Windows 7 media is only available upon request from HP Customer Support. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version.

For detailed Windows 7 OS hardware support information see <a href="http://h10032.www1.hp.com/ctg/Manual/c05857891.pdf">http://h10032.www1.hp.com/ctg/Manual/c05857891.pdf</a>.

#### **Available Processors**

Name	Cores	Clock Speed (GHz)	Cache (MB)	Memory Speed (MT/s)	Hyper- Threading	Featuring Intel® vPro™ Technology	Intel® Turbo Boost Technology¹	TDP (W)
Intel® Xeon® Platinum 8180 processor	28	2.5	38.50	2666	YES	YES	3.2, 3.8	205
Intel® Xeon® Platinum 8160 processor	24	2.1	33.00	2666	YES	YES	2.8, 3.7	150
Intel® Xeon® Gold 6152 processor	22	2.1	30.25	2666	YES	YES	2.8, 3.7	140
Intel® Xeon® Gold 6154 processor	18	3.0	24.75	2666	YES	YES	3.7, 3.7	200
Intel® Xeon® Gold 6148 processor	20	2.4	27.50	2666	YES	YES	3.1, 3.7	150
Intel® Xeon® Gold 6146 processor	12	3.2GHz	24.75	2666	YES	YES	YES	165
Intel® Xeon® Gold 6144 processor	8	3.5GHz	24.75	2666	YES	YES	YES	150
Intel® Xeon® Gold 6142 processor	16	2.6	22.00	2666	YES	YES	3.3, 3.7	150
Intel® Xeon® Gold 6140 processor	18	2.3	24.75	2666	YES	YES	3.0, 3.7	140
Intel® Xeon® Gold 6138 processor	20	2.0	27.5	2666	YES	YES	YES	125
Intel® Xeon® Gold 6136 processor	12	3.0	24.75	2666	YES	YES	3.6, 3.7	150
Intel® Xeon® Gold 6134 processor	8	3.2	24.75	2666	YES	YES	3.7, 3.7	130



## Overview

Intel® Xeon® Gold 6132 processor	14	2.6	19.25	2666	YES	YES	3.3, 3.7	140
Intel® Xeon® Gold 6130 processor	16	2.1	22.00	2666	YES	YES	2.8, 3.7	125
Intel® Xeon® Gold 6128 processor	6	3.4	19.25	2666	YES	YES	3.7, 3.7	115
Intel® Xeon® Gold 5120 processor	14	2.2	19.25	2400	YES	YES	2.6, 3.2	105
Intel® Xeon® Gold 5118 processor	12	2.3	16.50	2400	YES	YES	2.7, 3.2	105
Intel® Xeon® Gold 5115 processor	10	2.4	13.75	2400	YES	YES	YES	85
Intel® Xeon® Gold 5122 processor	4	3.6	16.50	2666	YES	YES	3.7, 3.7	105
Intel® Xeon® Silver 4116 processor	12	2.1	16.50	2400	YES	YES	2.4, 3.0	85
Intel® Xeon® Silver 4114 processor	10	2.2	13.75	2400	YES	YES	2.5, 3.0	85
Intel® Xeon® Silver 4112 processor	4	2.6	8.25	2400	YES	YES	2.9, 3.0	85
Intel® Xeon® Silver 4110 processor	8	2.1GHz	11.00	2400	YES	YES	YES	85
Intel® Xeon® Silver 4108 processor	8	1.8	11.00	2400	YES	YES	2.1, 3.0	85
Intel® Xeon® Bronze 3106 processor	8	1.7	11.00	2133	NO	YES	N/A	85
Intel® Xeon® Bronze 3104 processor	6	1.7	8.25	2133	NO	YES	N/A	85

<sup>1</sup>The specifications shown in this column represent the following: (all core maximum turbo frequency, one core maximum turbo frequency). Processors that do not have turbo functionality are denoted as N/A.

### **Available Processors**

**Disclaimers** 

Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

Color Black

Convertibility No

**Expansion Slots (see** more details)

Slot 0:

system board section for Mechanical-only, for use with devices that require only rear bulkhead mounting or when 2<sup>nd</sup> CPU riser is installed

PCI Express Gen3 x4 - CPU with open-ended connector\*

Slot 2:

PCI Express Gen3 x16 - CPU



## Overview

#### Slot 3:

PCI Express Gen3 x4 - PCH with open-ended connector\*

#### Slot 4:

PCI Express Gen3 x8 - CPU with open-ended connector (slot converts to x4 electrical when SSD is installed in 2nd M.2 slot)\*

#### Slot 5:

PCI Express Gen3 x16 - CPU

#### Slot 6:

PCI Express Gen3 x4 - PCH with open-ended connector\*

M.2 PCIe Gen 3 x4 - CPU up to 80mm storage devices

#### M.2 Slot 2:

M.2 PCIe Gen 3 x4 - CPU up to 80mm storage devices

\* Open-ended connector allows a greater bandwidth (e.g. x16) card to be installed physically into a lower bandwidth connector/slot.

## **Expansion Bays (see** storage section for more 2 external 5.25" bays details)

2 internal 3.5" bays (with acoustic dampening rail assemblies pre-installed)

- 3rd and 4th 3.5" HDD each occupy one external bay
- 3rd and 4th 2.5" HDD/SSD occupy a single external bay within a 2:1 carrier)

1 dedicated 9.5mm slim optical disk drive bay

#### Front I/O

- Base: Power button, 1 Headset audio port, 4 USB 3.1 G1 Type A (1 charging)
- Premium (optional): Power button, 1 Headset audio port, 2 USB 3.1 G2 Type C™, 2 USB 3.1 G1 Type A (1 charging)
- Optional: SD reader

#### Internal I/O

1 USB 3.1 G1 (aka USB 3.0) single-port header, 1 USB 2.0 single-port header and 1 USB 2.0 dual-port

header

Rear I/O

6 USB 3.1 G1 (aka USB 3.0) Type A ports, 2 1Gbe LAN ports (1x supporting Intel® AMT), Audio: 1 Line out, 1 Line in (Line in can be retasked as microphone), 1 PS/2 mouse port, 1 PS/2 keyboard port, 1

Rear power button

Optional: 1 serial port (cable up to rear bulkhead)

#### Interfaces Supported

SD card reader (optional)

6-channel SATA interface (6 @ 6.0 Gb/s)

6 channels are eSATA configurable for use with eSATA CTO/AMO Kit (No hot plug / hot swap

supported)

USB 2.0, USB 3.1 G1 (aka USB 3.0), USB 3.1 G2 (optional)

#### **On-board RAID Support**

SATA RAID 0 Striped Array Configuration SATA RAID 1 Mirrored Array Configuration SATA RAID 10 Striped/Mirrored Configuration

### **Chassis Dimensions (H x** H: 17.5" (445mm)

WxD)

W: 6.65" (169mm) D: 18.3" (465mm)



## Overview

**Packaged Dimensions** H: 24" (610mm)

W: 12.3" (313mm) D: 23.3" (593mm)

Rack Dimensions 4U

**Weight** Exact weights depend upon configuration (System weight only).

Minimum: 13.1 kg (29 lbs.) Standard: 13.6 kg (30.1 lbs.) Maximum: 23.9 kg (52.7 lbs.)

**Temperature** Operating: 5° to 35°C (40° to 95°F)

Non-operating: -40° to 60°C (-40° to 140°F)

Note: Above 1524 m (5,000 feet) altitude, maximum operating temperature is reduced by 1°C (1.8°F)

per 305 m (1,000 feet) elevation increase

**Humidity** Operating: 10% to 85% relative humidity, non-condensing, 35° C maximum wet bulb

Non-operating: 10% to 90% relative humidity, non-condensing, 35° C maximum wet bulb

Maximum Altitude (non-

pressurized)

Operating: 3,048m (10,000ft) Non-operating: 9,144m (30,000ft)

Note: Above 1524 m (5,000 feet) altitude, maximum operating temperature is reduced by 1° C (1.8° F)

per 305 m (1,000 feet) elevation increase

**Power Supply** 1000 watts wide-ranging, active Power Factor Correction, 90% Efficient, with 2X 6-pin graphics power

cables (graphics power cables are 6/8-pin convertible)

The Z6 G4 1000W power supply efficiency report can be found at this link:

https://plugloadsolutions.com/psu\_reports/HP\_D15-1K0P1A\_1000W\_ECOS%204838\_Report.pdf

Workstation ISV

See the latest list of certifications at

Certifications http://www8.hp.com/us/en/campaigns/workstations/industries-and-partners.html



## **Supported Components**

Processors		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Intel® Xeon® Scalable CPU				
	Intel® Xeon® Platinum 8180 processor	Υ	N	2DL53AV	
	Intel® Xeon® Platinum 8160 processor	Υ	Υ	2DL51AV	
	Intel® Xeon® Gold 6152 processor	Υ	Υ	2DL48AV	
	Intel® Xeon® Gold 6154 processor	Υ	N	2DL50AV	
	Intel® Xeon® Gold 6148 processor	Υ	Υ	2DL46AV	
	Intel® Xeon® Gold 6146 processor	Υ	Υ	2SQ66AV	
	Intel® Xeon® Gold 6144 processor	Υ	Υ	2SQ65AV	
	Intel® Xeon® Gold 6142 processor	Υ	Υ	2DL44AV	
	Intel® Xeon® Gold 6140 processor	Υ	Υ	2DL42AV	
	Intel® Xeon® Gold 6138 processor	Υ	Υ	3JN82AV	
	Intel® Xeon® Gold 6136 processor	Υ	Υ	2DL40AV	
	Intel® Xeon® Gold 6134 processor	Υ	Υ	2DL38AV	
	Intel® Xeon® Gold 6132 processor	Υ	Υ	2DL36AV	
	Intel® Xeon® Gold 6130 processor	Υ	Υ	2DL34AV	
	Intel® Xeon® Gold 6128 processor	Υ	Υ	2DL32AV	
	Intel® Xeon® Gold 5120 processor	Υ	Υ	2DL28AV	
	Intel® Xeon® Gold 5118 processor	Υ	Υ	2DL26AV	
	Intel® Xeon® Gold 5115 processor	Υ	Υ	4NA01AV	
	Intel® Xeon® Gold 5122 processor	Υ	Υ	2DL30AV	
	Intel® Xeon® Silver 4116 processor	Υ	Υ	2DL24AV	
	Intel® Xeon® Silver 4114 processor	Υ	Υ	2DL22AV	
	Intel® Xeon® Silver 4112 processor	Υ	Υ	2DL20AV	
	Intel® Xeon® Silver 4110 processor	Υ	Υ	3JN81AV	
	Intel® Xeon® Silver 4108 processor	Υ	Υ	2DL18AV	
	Intel® Xeon® Bronze 3106 processor	Υ	Υ	2DL16AV	
	Intel® Xeon® Bronze 3104 processor	Υ	Υ	2DL14AV	
	AND DECEMBER OF THE PROPERTY O	C			

\*Multi-Core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. 64-bit computing system required. Performance will vary depending on your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

Monitors / Displays		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP Z Display Z22n G2		Υ	1JS05AA	
	HP Z Display Z23n G2		Υ	1JS06AA	
	HP Z Display Z24i G2		Υ	1JS08AA	
	HP Z Display Z24n G2		Υ	1JS09AA	
	HP Z Display Z24nf G2		Υ	1JS07AA	
	HP Z Display Z27n G2		Υ	1JS10AA	



## **Supported Components**

HP Z Display Z27s (4K display)

J3G07AA

Supported by all operating systems available from HP Screen size measured diagonally

## Storage / Hard Drives

SAS Hard Drives		_		Option	_
	SAS Hard Drives for HP Workstations	Factory Configured	Option Kit	Kit Part Number	Support Notes
	HP 300GB 15k SAS SFF	Υ	Υ	L5B74AA	
	NOTE: SAS controller add-in card required				

SATA Hard Drives		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	SATA (Serial ATA) Hard Drives for HP Workstations				
	500GB SATA 7200RPM 6Gb/s 3.5" HDD	Υ	Υ	LQ036AA	
	500GB SATA 7200RPM 6Gb/s OPAL2 SFF 3.5" HDD	Υ	Υ	D8N29AA	
	1TB SATA 7200RPM 3.5" HDD	Υ	Υ	LQ037AA	
	1TB SATA 7200RPM Ent 3.5" HDD	Υ	Υ	WOR10AA	
	2TB SATA 7200RPM HDD	Υ	Υ	QB576AA	
	4TB SATA 7200RPM Ent 3.5" HDD	Υ	Υ	K4T76AA	
	NOTES:				

Up to (4) 3.5-inch 7200 rpm SATA drives:  $500 \, \text{GB}$ , 1.0, 2.0,  $4.0 \, \text{TB}$ ; maximum system HDD storage:  $16.0 \, \text{TB}$ 



## **Supported Components**

SATA Solid State Drives	HP Solid State Drives (SSDs) for Workstations	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP 256GB SATA SSD	Υ	Υ	A3D26AA	
	HP 512GB SATA SSD	Υ	Υ	D8F30AA	
	HP 1TB SATA SSD	Υ	Υ	F3C96AA	
	HP 2TB SATA SSD	Υ	Υ	Y6P08AA	
	HP 256GB SATA SED OPAL2 SSD	Υ	Υ	G7U67AA	
	HP 512GB SATA SED OPAL2 SSD	Υ	Υ	N8T26AA	
	HP 240GB SATA Enterprise SSD	Υ	Υ	T3U07AA	
	HP 480GB SATA Enterprise SSD	Υ	Υ	T3U08AA	

PCIe Solid State Drives		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	PCIe SSDs for HP Workstations				
	HP Z Turbo Drive 256GB MLC Z4/Z6 G4 SSD Kit	Υ	Υ	1PD56AA	
	HP Z Turbo Drive 512GB MLC Z4/Z6 G4 SSD Kit	Υ	Υ	1PD57AA/AT	
	HP Z Turbo Drive 1TB MLC Z4/Z6 G4 SSD Kit	Υ	Υ	1PD58AA	
	HP Z Turbo Drive 256GB TLC Z4/Z6 G4 SSD Kit	Υ	Υ	1PD59AA/AT	
	HP Z Turbo Drive 512GB TLC Z4/Z6 G4 SSD Kit	Υ	Υ	1PD60AA	
	HP Z Turbo Drive 1TB TLC Z4/Z6 G4 SSD Kit	Υ	Υ	1PD61AA	
	HP Z Turbo Drive 256GB Z4/Z6 G4 SED Kit	Υ	Υ	2SA31AA	
	HP Z Turbo Drive 512GB Z4/Z6 G4 SED Kit	Υ	Υ	2SA32AA	
	HP Z Turbo Drive Quad Pro				
	HP Z Turbo Drive Quad Pro 2x256GB PCIe SSD	Υ	Υ	N2M98AA	1
	HP Z Turbo Drive Quad Pro 2x512GB PCIe SSD	Υ	Υ	N2M99AA	1
	HP Z Turbo Drive Quad Pro 2x1TB PCIe SSD	Υ	Υ	Т9Н99АА	1
	HP Z Turbo Drive Quad Pro 256GB SSD module	N	Υ	N2N00AA	2
	HP Z Turbo Drive Quad Pro 512GB SSD module	N	Υ	N2N01AA	2
	HP Z Turbo Drive Quad Pro 1TB SSD module	N	Υ	T9J00AA	2
	Intel® 905p Series SSD (Opatane SSD)				
	Intel® Optane SSD 905p 280GB AiC**,***	Υ	Υ	2SC47AA	
	Intel® Optane SSD 905p 480GB AiC**,***	Υ	Υ	2SC48AA	

Note 1: Dual M.2 SSD modules plus carrier

Note 2: M.2 SSD module only, designed to be installed into Quad Pro carrier



<sup>\*\*</sup> PCIe card installed in standard PCIe x4 slot

<sup>\*\*\*</sup> Intel® Optane SSD Available Fall 2018

## **Supported Components**

Hard Drive Controllers		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	SAS Controller				
	MicroSemi SmartHBA2100-4i4e SAS Controller	Υ	Υ	1FV90AA	

## **Graphics**

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes	Supported # of cards
Graphics Cable Adapters					
HP DisplayPort to VGA Adapter	Υ	Υ	AS615AA		
HP DisplayPort to HDMI Adapter	Υ	Υ	K2K92AA		
HP DisplayPort to Dual Link DVI Adapter	Υ	Υ	NR078AA		1
HP DisplayPort to DVI-D Adapter	Υ	Υ	FH973AA		1
HP DisplayPort to DVI-D Adapter (2-pack)	Υ	N			1
HP DisplayPort to DVI-D Adapter (4-pack)	Υ	N			1
HP DisplayPort to DVI-D Adapter (6-pack)	Υ	N			1
NVIDIA® SLI 3-slot Graphics Connector	Υ	Υ	2YY85AA		1
Entry 3D					
NVIDIA® Quadro® P400 1st GFX 2GB Graphics	Υ	Υ	1ME43AA/AT		2
NVIDIA® Quadro® P600 1st GFX 2GB Graphics	Υ	Υ	1ME42AA/AT		2
AMD FirePro™ W2100 2GB Graphics	Υ	Υ	J3G91AA/AT		2
Mid-range 3D					
NVIDIA® Quadro® P1000 1st GFX 4GB Graphics	Υ	Υ	1ME01AA/AT		2
NVIDIA® Quadro® P2000 1st GFX 5GB Graphics	Υ	Υ	1ME41AA/AT		2
AMD Radeon™ Pro WX 3100 4GB Graphics	Υ	Υ	2TF08AA		2
AMD Radeon™ Pro WX 4100 4GB Graphics	N	Υ	ZOB15AA/AT		2
High End 3D					
NVIDIA® Quadro® P4000 1st GFX 8GB Graphics	Υ	Υ	1ME40AA/AT		2
NVIDIA® Quadro® P5000 1st GFX 16GB Graphics	Υ	Υ	ZOB13AA/AT		2
NVIDIA® Quadro® P6000 1st GFX 24GB Graphics	Υ	Υ	ZOB12AA/AT		1
AMD Radeon™ Pro WX 7100 1st GFX 8GB Graphics	Υ	Υ	ZOB14AA/AT		2

**NOTE:** NVIDIA® Quadro® GP100 and AMD Radeon™ Pro WX 9100 support available the first half of 2018

Memory	СТО	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	DDR4-2666 ECC Registered DIMMs				
	8GB (1x8GB) DDR4-2666 ECC Reg 1CPU Memory	Υ	Υ	1XD84AA/AT	
	16GB (2x8GB) DDR4-2666 ECC Reg 1CPU Memory	Υ			
	24GB (3x8GB) DDR4-2666 ECC Reg 1CPU Memory	Υ			
	32GB (4x8GB) DDR4-2666 ECC Reg 1CPU Memory	Υ			
	48GB (6x8GB) DDR4-2666 ECC Reg 1CPU Memory	Υ			



## **Supported Components**

16GB (1x16GB) DDR4-2666 ECC Reg 1CPU Memory	N	Υ	1XD85AA/AT
32GB (2x16GB) DDR4-2666 ECC Reg 1CPU Memory	Υ		
48GB (3x16GB) DDR4-2666 ECC Reg 1CPU Memory	Υ		
64GB (4x16GB) DDR4-2666 ECC Reg 1CPU Memory	Υ		
96GB (6x16GB) DDR4-2666 ECC Reg 1CPU Memory	Υ		
32GB (1x32GB) DDR4-2666 ECC Reg 1CPU Memory	N	Υ	1XD86AA/AT
64GB (2x32GB) DDR4-2666 ECC Reg 1CPU Memory	Υ		
96GB (3x32GB) DDR4-2666 ECC Reg 1CPU Memory	Υ		
128GB (4x32GB) DDR4-2666 ECC Reg 1CPU Memory	Υ		
192GB (6x32GB) DDR4-2666 ECC Reg 1CPU Memory	Υ		
32GB (4x8GB) DDR4-2666 ECC Reg 2CPU Memory	Υ		
48GB (6x8GB) DDR4-2666 ECC Reg 2CPU Memory	Υ		
64GB (8x8GB) DDR4-2666 ECC Reg 2CPU Memory	Υ		
96GB (12x8GB) DDR4-2666 ECC Reg 2CPU Memory	Υ		
64GB (4x16GB) DDR4-2666 ECC Reg 2CPU Memory	Υ		
96GB (6x16GB) DDR4-2666 ECC Reg 2CPU Memory	Υ		
128GB (8x16GB) DDR4-2666 ECC Reg 2CPU Memory	Υ		
192GB (12x16GB) DDR4-2666 ECC Reg 2CPU Memory	Υ		
128GB (4x32GB) DDR4-2666 ECC Reg 2CPU Memory	Υ		
192GB (6x32GB) DDR4-2666 ECC Reg 2CPU Memory	Υ		
256GB (8x32GB) DDR4-2666 ECC Reg 2CPU Memory	Υ		
384GB (12x32GB) DDR4-2666 ECC Reg 2CPU Memory	Υ		

#### **NOTES:**

For details on the supported memory configurations on the HP Z6 G4 Workstation, please refer to the System Technical Specifications - System Board section of this document.

Each processor supports up to 6 channels of DDR4 memory. To realize full performance at least 1 DIMM must be inserted into each channel.

With single-processor configurations, 6 DIMM slots are available. 6 additional DIMM slots are available with the 2nd CPU & Memory Module.

The CPUs determine the speed at which the memory is clocked. If a 2400MT/s capable CPU is used in the system, the maximum speed the memory will run at is 2400MT/s, regardless of the specified speed of the memory.

ONLY registered DDR4 DIMMs are supported. DDR3 DIMMs ARE NOT SUPPORTED.

**NOTE 2:** Z6 G4 configurations that include a 2<sup>nd</sup> CPU require the HP Z6 Memory Cooling Solution, which is available both CTO (2JA81AV) and AMO (2HW44AA). Z6 G4 configurations that include greater than 32GB total system memory require the HP Z6 Memory Cooling Solution, which is available both CTO (2JA81AV) and AMO (2HW44AA).

## **Multimedia and Audio Devices**



## **Supported Components**

## **Multimedia and Audio Devices**

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
Integrated Realtek HD ALC221 Audio	Υ	N		

## **Optical and Removable Storage**

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP SlimTray Optical Drives		operon and		
HP 9.5mm Slim Blu Ray Disc Writer	Υ	Υ	K3R65AA	
HP 9.5mm Slim DVD ROM	Υ	Υ	K3R63AA	
HP 9.5mm Slim DVD Writer	Υ	Υ	K3R64AA	
HP SD Card Reader				
HP SD 4 Card Reader	Υ	Υ	Y0L99AA	

Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

With Blu-ray, certain disc, digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this workstation.

## **Networking and Communications**

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP i350-T2 PCIe Dual Port Gigabit NIC	Υ	Υ	V4A91AA	
Intel® i350-T4 PCIe 4-Port Gigabit NIC	N	Υ	W8X25AA	
Intel® Ethernet I210-T1 PCIe x1 Gb NIC	Υ	Υ	E0X95AA	
HP Dual Port 10GBase-T NIC Module	Υ	Υ	1QL49AA	
Intel® 8265 802.11 a/b/g/n/ac + BT PCIe WLAN	N	Υ	1QL48AA	
Intel® X550-T2 10GbE Dual Port NIC	Υ	Υ	1QL46AA	
Intel® X710-DA2 10GbE SFP+ Dual Port NIC	Υ	Υ	1QL47AA	1
HP 10GbE SFP+ SR Transceiver	Υ	Υ	C3N53AA	

Note 1: Windows 7 is NOT supported

## **Racking and Physical Security**



## **Supported Components**

## **Racking and Physical Security**

Factory Configured	Option Kit	Option Kit Part Number	Support Notes
Υ	N		
Υ	N		
N	Υ	2HW42AA	
N	Υ	T1A62AA	
	Configured Y Y N	Configured Kit Y N Y N N Y N	Factory Option Kit Part Configured Kit Number Y N Y N N Y 2HW42AA

## **Input Devices**

			Option Kit	
	Factory Configured	Option Kit	Part Number	Support Notes
HP Wireless Business Slim Keyboard and Mouse	Υ	Υ	N3R88AA	
Business Slim PS/2 Wired Keyboard	Υ	Υ	N3R86AA	
USB Business Slim Wired Keyboard	Υ	Υ	N3R87AA	
USB Premium Wired Keyboard	Υ	Υ	Z9N40AA	
USB Wired SmartCard CCID Keyboard	Υ	Υ	E6D77AA	
3Dconnexion CADMouse	Υ	Υ	M5C35AA	
HP Optical USB Mouse	Υ	Υ	QY777AA	
HP PS/2 Mouse	Υ	Υ	QY775AA	
HP USB Hardened Mouse	Υ	Υ	P1N77AA	

## **Other Hardware**

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP ENERGY STAR® Certified Configuration	Υ			
HP Z Premium Front I/O 2xUSB-A 2xUSB-C	Υ	Υ	1XM32AA	
HP Z6 G4 Memory Cooling Solution	Υ	Υ	2HW44AA	Note 1
HP Internal USB Port Kit	N	Υ	EM165AA	Note 2
HP eSATA 2 port PCI Bulkhead Kit	Υ	Υ	GM110AA	
HP Serial Port Adapter	Υ	Υ	PA716A	
HP Workstation Mouse Pad	Υ			

**Note 1:** Z6 G4 configurations that include a 2nd CPU require the HP Z6 Memory Cooling Solution, which is available both CTO (2JA81AV) and AMO (2HW44AA). Z6 G4 configurations that include greater than 32GB total system memory require the HP Z6 Memory Cooling Solution, which is available both CTO (2JA81AV) and AMO (2HW44AA).

**Note 2:** The HP Internal USB Port kit has a single USB 2.0 type A connector.

Software		Factory		Option Kit Part	
		Configured	Option Kit	Number	Support Notes
	Sobey Video Editing SW	Υ	N		



**Supported Components** 

SW HP RGS for Z

Υ

Ν



## **Supported Components**

## **Operating Systems**

**Support Notes** 

Windows 10 Pro 64

Windows 7 Professional 64-bit Note 3, 4

Windows 10 Downgrade to Windows 7

HP Linux® Installer Kit

Note 2

Red Hat® Enterprise Linux® (RHEL) Workstation - Paper License (1yr)

Note 1

**NOTE 1**: This second OS must be ordered with the HP Linux® Installer Kit as the first OS.

**NOTE 2**: includes drivers for 64-bit OS versions of RHEL 6 & 7, SUSE Linux® Enterprise Desktop 11 and Ubuntu 14.04. For detailed Linux® OS/hardware support information, see: http://www.hp.com/support/linux\_hardware\_matrix

**NOTE 3:** downgrade media available by request from HP Support. For detailed Windows 7 OS hardware support information see http://h10032.www1.hp.com/ctg/Manual/c05857891.pdf.

**NOTE 4:** Windows 10 is preinstalled. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version



## **System Technical Specifications**

## System Board

System Board Form Main System Board: Factor 24 x 31 cm

9.6 x 12.2 inches

2nd CPU/Memory Board (optional):

14.9 x 29.2 cm 5.85 x 11.50 inches

**Processor Socket** FCLGA3647 (Socket P)

1st CPU on system board

2nd CPU on optional 2nd CPU/Memory Module UPI: Up to 10.4GT/second, depending on processor

Chipset Intel® C622 Chipset
Super I/O Controller Nuvoton SIO15

Memory Expansion

**CPU Bus Speed** 

Slots

6 on system board(CPU0) + 6 on optional 2nd CPU/Memory Module(CPU1)

Memory Type DDR4, RDIMM (Registered), ECC: 8GB, 16GB and 32GB

Supported

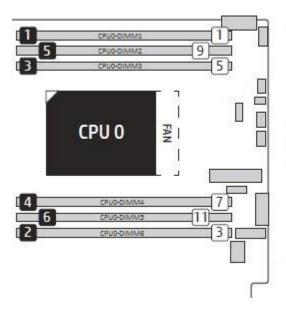
**Memory Modes** NUMA (Non-Uniform Memory Architecture), Memory Node Interleave

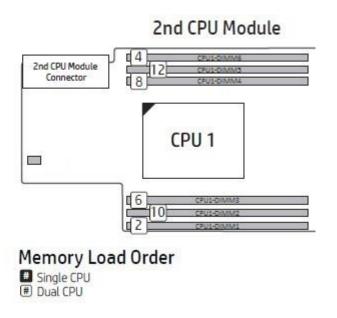
Memory Speed 2133MT/s, 2400MHz and 2666MT/s

Supported

#### **Memory Loading Order:**

## Load Order for Single and Dual Processor Configuration





**Maximum Memory** Supports up to 384GB with two processors.



## System Technical Specifications

## **Memory Configuration** (Supported)

- Only Registered ECC DIMMs are supported.
- Do not install memory modules into memory slots if corresponding processor is not installed.
- Dual processor configurations with memory modules installed for only one processor is not supported.

#### **Notes**

For systems installed with Microsoft Windows 7 (Ultimate, Enterprise or Pro), the maximum accessible system memory is 192GB

#### **PCI Express Connectors Slot 0:**

Mechanical-only, for use with devices that require only rear bulkhead mounting or when 2<sup>nd</sup> CPU riser is installed

#### Slot 1:

PCI Express Gen3 x4 - CPU with open-ended connector\*

#### Slot 2:

PCI Express Gen3 x16 - CPU

#### Slot 3:

PCI Express Gen3 x4 - PCH with open-ended connector\*

PCI Express Gen3 x8 - CPU with open-ended connector (slot converts to x4 electrical when SSD is installed in 2nd M.2 slot)\*

#### Slot 5:

PCI Express Gen3 x16 - CPU

PCI Express Gen3 x4 - PCH with open-ended connector\*

#### M.2 Slot 1:

M.2 PCIe Gen 3 x4 - CPU up to 80mm storage devices

#### M.2 Slot 2:

M.2 PCIe Gen 3 x4 - CPU up to 80mm storage devices

\* Open-ended connector allows a greater bandwidth (e.g. x16) card to be installed physically into a lower bandwidth connector/slot.

## **Supported Drive** Interfaces

**SATA** 6 SATA @6Gb/s, supports RAID 0, 1 and NCQ.

Factory integrated RAID is Microsoft Windows only.

Serial Attached SCSI Requires Optional PCIe card

### **Factory Configured**

RAID

RAID 0 configuration - striped array

RAID 1 configuration - mirrored array

RAID 10 striped and mirrored array

\*HW RAID functionality not supported by Linux®. Use SW RAID functionality

provided in the Red Hat® Operating system instead.

**Integrated Graphics** No

**Network Controller** Integrated Intel® I219LM GbE LAN

## **System Technical Specifications**

Supports the following management functionalities: Intel® AMT11.2, TXT, DASH

1.1, WOL, VLAN, and PXE 2.1

Integrated Intel X722 for 1GbE
Data rates supported: 1000 Mb/s

Compliance IEEE 802.1as/1588v2, 802.1p, 802.1Q, 802.3, 802.3ab, 802.3az,

802.3x

Up to 16 UDP/TCP programmable filters

Bus architecture: PCIe 3.0
UEFI and PXE Boot ROM support
Intel iWARP Support (RDMA)
Network transfer rates:

1000BASE-T (full-duplex) 2000 Mb/s

Management capabilities: WOL (Excluding Max Power Savings), auto MDI

crossover, PXE, Quad Hash filtering, RSS, Advanced cable

diagnostics

External SATA (eSATA) Supported on all SATA ports configurable with optional eSATA\* cable kit

\* hot plug / hot swap not supported with eSATA

**USB Connector(s)** Front Front USB depends on which FIO module is selected:

- Standard: 4 USB 3.1 G1 Type A (1 charging)

- Premium: 2 USB 3.1 G2 Type C, 2 USB 3.1 G1 Type A (1 charging)

Rear 6 USB 3.1 G1 Type A

**Internal** 1 USB 3.1 G1 single-port header

1 USB 2.0 single-port header 1x USB 2.0 dual-port header

HD Integrated Audio Realtek ALC221

Flash ROM Yes

**CPU Fan Header** One for each CPU socket

Rear Chassis Fan Header Yes Front PCI Fan Header Yes CMOS Battery Holder - Yes

Lithium

Integrated Trusted Trusted Platform Module (TPM) 2.0 (Infineon SLB 9670)

Platform Module Common Criteria EAL4+ Certified

Convertible to FIPS 140-2 Certified mode through firmware v7.80

TPM Certified products list:

https://trustedcomputinggroup.org/membership/certification/tpm-certified-products/

Power Supply Headers Yes
Power Switch, Power Yes

LED & Hard Drive LED

Header

**Clear Password Jumper** Yes

Serial Port 1 internal header

Parallel Port No

**Keyboard/Mouse** USB or PS/2

**Hood Lock Header** Yes **Hood Sensor Header** Yes

Memory Fan 1 Memory Fan Header per CPU

AUX IN (audio) No

## **System Technical Specifications**

**Z6 Required Power Supply Info** 

**Power Supply**1000W 90% Efficient, Custom PSU
(Wide Ranging, Active PFC)

Operating Voltage Range 90–269 VAC

**Rated Voltage Range**100-127 VAC
200-240 VAC
118 VAC

**Rated Line Frequency** 50-60 Hz 400 Hz **Operating Line Frequency Range** 47-66 Hz 393-407 Hz

12 A @ 100-127 VAC

Rated Input Current 6.3 A @ 200-240 VAC 12A @ 118 VAC

**Heat Dissipation (Configuration and software dependent)**Typical = 2467 btu/hr
Maximum = 4112 btu/hr

Power Supply Fan 80x25 mm variable speed

ENERGY STAR® Qualified Yes (Configuration dependent)

Yes, 90% Efficient The Z6 G4 1000W power supply efficiency report can be found at this link:

80 PLUS® Compliant https://plugloadsolutions.com/psu\_reports/HP\_D151K0P1A\_1000W\_ECOS%204838\_Report.pdf

FEMP Standby Power Compliant @115V
(<1W in S5 – Power Off)

EuP Compliant @ 230V
Yes

(<0.5 W in S5 – Power Off)

CECP Compliant @ 220V

(<4W in S3 – Suspend to RAM)

Yes; Configuration dependent

Power Consumption in sleep mode
(as defined by ENERGY STAR®) – Suspend to RAM

(S3) <= 20W

(Instantly Available PC)

Built-in Self Test LED Yes

Surge Tolerant Full Ranging Power Supply
(withstands power surges up to 2000V)

Sensor Header Integrated in Front User Interface (Power Switch, Power LED, HDD LED,

Speaker) Cable

Integrated Gigabit Ethernet Integrated Intel® I-218 Gbit LAN

Clear CMOS Button Yes

## **System Technical Specifications**

## **System Configuration**

Example Z6 G4	Processor	1x Intel Xeon	3104 (Six-core)						
Configuration #1	Memory	1x 8GB DDR4-	2666 (Register	ed DIMM)					
	Graphics	1x NVIDIA Qua	dro P400						
	Disks / Optical	1x 500GB SAT	A 7200 ; 1x Slin	n DVD-ROM SA	<b>NTA</b>				
	Power Supply	1000W 90% c	ustom PSU						
	Other	NA							
		115	115 VAC 230 VAC 100 VAC						
Energy Consumption		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled		
	Windows Idle (S0)	54	.109	54.	586	54.	906		
	Windows Busy Typ(S0)	94.256 94.275 94.043							
	Windows Busy Max (S0)	95	.992	95.	268	95.	643		
	Sleep (S3)	6.219	6.205	6.319	6.306	6.334	6.239		
	Off (S5)	3.354	3.343	3.521	3.341	3.350	3.342		
	Zero Power Mode (ErP)	0.	209	0.3	388	0.1	95		
		115	5 VAC	230	VAC	100	VAC		
<b>Heat Dissipation</b>		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled		
(Btu/hr)	Windows Idle (S0)	184	l.619	186	.247	187	.339		
	Windows Busy Typ(S0)	321	.601	321.666		320.875			
	Windows Busy Max (S0)	sy Max (S0) 327.524 325.054					.334		
	Sleep (S3)	21.219	21.171	21.561	21.516	21.611	21.287		
	Off (S5)	11.444	11.406	12.014	11.399	11.430	11.403		
	Zero Power Mode (ErP)	0.	713	1.3	323	0.6	65		

Example Z6 G4	Processor	1x Intel Xeon	4108 (Eight-co	re)					
Configuration #2	Memory	4x 8GB DDR4	-2666 (Registe	red DIMM)					
	Graphics	1x NVIDIA Qua	adro P2000						
	Disks / Optical	2x 1TB SATA 7	7200 ; 1x Slim D	VDRW SATA					
	Power Supply	1000W 90% c	ustom PSU						
	Other	NA							
Energy Consumption		115	115 VAC 230 VAC 100 VAC						
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled		
	Windows Idle (S0)	61.661 61.531		531	61.354				
	Windows Busy Typ(S0)	168.665 167.375		166.535					
	Windows Busy Max (S0)	166.097		163.682		169.674			
	Sleep (S3)	7.231	7.177	7.229	7.217	7.324	7.248		
	Off (S5)	3.376	3.366	3.527	3.512	3.354	3.350		
	Zero Power Mode (ErP)	0.	211	0.3	886	0.195			
		115	5 VAC	230	VAC	100	VAC		
<b>Heat Dissipation</b>		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled		
(Btu/hr)	Windows Idle (S0)	210	).387	209	.944	209.340			



## **System Technical Specifications**

Windows	Busy Typ(S0)	575.485		571.	084	568.217	
Windows	Busy Max (S0)	576.959		575.543		578.928	
Sleep (S3	)	24.672	24.488	24.665	24.624	24.989	24.730
Off (S5)		11.519	11.484	12.034	11.983	11.443	11.430
Zero Pow	er Mode (ErP)	0.7	720	1.317		0.6	65

Example Z6 G4	Processor 1x Intel Xeon 6136 (Twelve-core)							
Configuration #3	Memory	6x 8GB DDR4	-2666 (Register	ed DIMM)				
ENERGY STAR	Graphics	1x NVIDIA Qua	adroP4000					
QUALIFIED	Disks/Optical	2x 1TB SATA	7200 ; 1x Slim D	VDRW SATA				
	Power Supply	1000W 90% c	ustom PSU					
	Other	NA						
Energy Consumption		115	5 VAC	230	VAC	100	VAC	
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	
	Windows Idle (S0)	79	.074	79.	109	79.	938	
	Windows Busy Typ(S0)	324	1.975	317	.991	327	.451	
	Windows Busy Max (S0)	(S0) 328.268 320.296 329.66						
	Sleep (S3)	7.847	7.756	7.878	7.826	7.931	7.852	
	Off (S5)	3.353	3.348	3.535	3.489	3.373	3.355	
	Zero Power Mode (ErP)	0.	206	0.3	886	0.1	96	
		115	5 VAC	230	VAC	100	VAC	
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled	
(Btu/hr)	Windows Idle (S0)	269	9.801	269	.920	272	.748	
	Windows Busy Typ(S0)	110	8.815	1084	1.985	1117	'.262	
	Windows Busy Max (S0)	112	0.051	1092	2.850	1124	1.827	
	Sleep (S3)	26.774 26.463 26.880 26.702 27.061 26.791						
	Off (S5)	11.441	11.426	12.061	11.904	11.509	11.447	
	Zero Power Mode (ErP)	0.	703	1.3	317	0.6	669	

Example Z6 G4	Processor	2x Intel Xeon	2x Intel Xeon 8160 (Dual 24-core)						
Configuration #4	Memory	12x 32GB DDF	2x 32GB DDR4-2666 (Registered DIMM)						
	Graphics	2x NVIDIA Qua	2x NVIDIA Quadro P5000						
	Disks / Optical	4x 2TB SATA 7	4x 2TB SATA 7200 ; 1x Slim DVDRW SATA						
	Power Supply	1000W 90% c	000W 90% custom PSU						
	Other	NA							
<b>Energy Consumption</b>		115	VAC	230	VAC	100	VAC		
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled		
	Windows Idle (S0)	112.	388	115	.635	112	.102		
	Windows Busy Typ(S0)								
	Windows Busy Max (S0)								
1	Sleep (S3)	14.208	13.833	14.698	14.487	15.176	13.886		



## **System Technical Specifications**

	Off (S5)	3.511	3.418	3.575	3.570	3.509	3.412
	Zero Power Mode (ErP)	0.2	87	0.3	887	0.2	272
		115	VAC	230	VAC	100	VAC
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled
(Btu/hr)	Windows Idle (S0)	383.	469	394	.547	382	.492
	Windows Busy Typ(S0)	1748	.120	1672	2.443	1797	'.800
	Windows Busy Max (S0)	2383	.446	2297	7.863	2410	).445
	Sleep (S3)	48.478	47.198	50.150	49.430	51.781	47.379
	Off (S5)	11.980	11.662	12.198	12.181	11.973	11.642
	Zero Power Mode (ErP)	0.979		1.321		0.928	

**NOTE:** Power consumption measurements do not take advantage of the Intel Turbo Boost Technology. As a result, power consumption measurements may be higher.

## **DECLARED NOISE EMISSIONS**

System Configuration	
(Entry level)	

Processor Info	Intel® Xeon® Gold 6130 processor 2.1GHz 12C CPU			
Memory Info	24GB (3x8GB) DDR4-2666 ECC Memory RDIMMs			
Graphics Info	1-NVIDIA® Quadro® P400 2GB			
Disks/Optical	1-500GB SATA 7200RPM 3.5" HDD / 1-HP 9.5mm Slim Blu Ray Disc Writer			
Power Supply	1000 W			

<b>Declared Noise Emissions</b> (in accordance with ISO 7779 and ISO 9296)		Sound Power (LWAd, bels)	<b>Deskside Sound Pressure</b> (LpAm, decibels)
	Idle	3.3	15
	Hard drive Operating (random reads)	3.5	18

<b>System Configuration</b>
(Mid-range)

Processor Info	Intel® Xeon® Platinum 8168 processor 2.7GHz 24C CPU
Memory Info	96GB (6x16GB) DDR4-2666 ECC Memory RDIMMs
Graphics Info	1-NVIDIA® Quadro® P6000 24GB
Disks/Optical	2-4TB 6Gb/s 7200RPM SATA HDD / 1-HP 9.5mm Slim Blu Ray Disc Writer
Power Supply	1000 W

Declared Noise Emissions (in accordance with ISO		<b>Sound Power</b> (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
7779 and ISO 9296)	Idle	3.8	23
	Hard drive Operating (random reads)	3.9	23

## System Technical Specifications

System Configuration	Processor Info	2-Intel® Xeon® Gold 6136 processor 3.0GHz 12C CPU
(High end)	Memory Info	192GB (12x16GB) DDR4-2666 ECC Memory RDIMMs
	Graphics Info	1-NVIDIA® Quadro® P6000 24GB
	Disks/Optical	2-4TB 6Gb/s 7200RPM SATA HDD / 1-HP 9.5mm Slim Blu Ray Disc Writer
	Power Supply	1000 W

<b>Declared Noise Emissions</b> (in accordance with ISO 7779 and ISO 9296)		<b>Sound Power</b> (LWAd, bels)	<b>Deskside Sound Pressure</b> (LpAm, decibels)
	Idle	3.8	23
	Hard drive Operating (random reads)	3.9	24

### **ENVIRONMENTAL DATA**

**Environmental** Requirements

**Temperature** Operating: 5° to 35° C (40° to 95° F)

Non-operating: -40° to 60° C (-40° to 140° F)

**Humidity** Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb

Non-operating: 10% to 90% RH, non-condensing, 35° C maximum wet bulb

**Maximum Altitude** Operating: 3,048 m (10,000 feet)

> Above 1524 m (5.000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation

Non-operating: 9,144 m (30,000 feet)

Shock (non-repetitive) Operating: ½-sine: 40g, 2-3ms (~62 cm/sec)

Non-operating: 1/2-sine: 160 cm/s, 2-3ms (~105g)

square: 422 cm/s, 20q

**Vibration** 

Operating random: 0.5g (rms), 5-300 Hz, up to 0.0025g2/Hz Non-operating random: 2.0g (rms), 5-500 Hz, up to 0.0150 g<sup>2</sup>/Hz

## **Physical Security and Serviceability**

**Access Panel** Tool-less

Includes system board and memory information.

Tool-less, no carrier or rails required **Hard Drives** Tool-less

Optional 5.25" external bay carriers

**Expansion Cards** Tool-less

**Processor Socket** 1st socket on main system board. 2nd socket on optional 2nd CPU/Memory Module.

**Blue User Touch Points** Yes, on primary serviceable components.

Color-coordinated Cables Yes

and Connectors

**Optical Drive** 

## System Technical Specifications

Memory Tool-less

**System Board** Torx T15 screws

2nd CPU/Memory Module: Tool-less

Dual Color Power/Failure LED = Yes Front of Computer LEDs

HDD Activity LED = Yes

**Configuration Record SW** Yes

Over-Temp Warning on

Yes, at POST screen on reboot

Restore CD/DVD Set

Screen

Yes, restores the computer to its original factory shipping image; can be obtained via HP Support.

**Dual Function Front** 

Yes, also acts as a reset switch when held for 4 seconds.

**Power Switch** 

**Padlock Support** Yes

Kensington Cable Lock (optional): Prevents entire system theft and system access. 3mm x 7mm slot at **Cable Lock Support** 

rear of system

**Universal Chassis Clamp** 

**Lock Support** 

Solenoid Lock and Hood

Sensor

Access Panel Solenoid Lock: Yes (optional). Activated remotely to prevent system entry. Access Panel Intrusion Sensor: Yes (optional).

Yes, user can prevent the workstation from writing to or booting from removable media.

Removable Media

Write/Boot Control

Power-On Password

Yes, prevents an unauthorized person from booting up the workstation

Setup Password

Yes, prevents an unauthorized person from changing the workstation configuration

3.3V Aux Power LED on

System PCA

Yes

NIC LEDs (integrated)

(Green & Amber)

Yes

**CPUs and Heatsinks** 

Power Supply Diagnostic Yes

LED

CPU heatsink removal requires a T-30 Torx screwdriver.

**Front Power Button** 

Yes

**Rear Power Button** 

Yes

**Front Power LED** 

Yes, white (normal), red (fault)

Front Hard Drive Activity Yes, white

Front ODD Activity LED Yes on device

Internal Speaker Yes

System/Emergency ROM

Recovers corrupted system BIOS.

Flash Recovery

**Cooling Solutions** Air cooled forced convection

**Power Supply Fans** 1 - 80 mm x 80 mm x 25 mm (non-serviceable)

**CPU Heatsink Fan** 1st CPU: 1 - 80mm

Optional 2nd CPU: 1 - 60mm x 25mm

Front memory fan: 1 - 80mm x 25mm **Memory Fan** 

> Memory duct blower: 1 - 90mm x 25mm 2nd CPU/Memory Module: 1 - 60mm x 25mm

## System Technical Specifications

**Chassis Fans** Front chassis fan: 1 - 120mm x 25mm

Rear chassis fan: 1 - 120mm x 25mm

**HP Vision Diagnostics** Offline Edition

HP PC Hardware Diagnostics (UEFI) enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing ESC then F2 upon the PC reboot, and is

available as a download from HP Support.

**Access Panel Key Lock ACPI-Ready Hardware** 

Yes, side panel barrel keylock (optional from the factory only) Advanced Configuration and Power Management Interface (ACPI).

Allows the system to wake from a low-power mode.

Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system

Trusted Platform Module Yes, Infineon TPM 2.0 Certified

Chip

**Integrated Chassis** 

Handles

Yes, Front handle and dedicated rear recess

**Power Supply** Requires T15 Torx or flat blade screwdriver

**PCIe Card Retention** 

Yes, tool-less Rear (all)

Middle (full-height cards)

Front (full-length cards with extender)

Flash ROM Yes **Diagnostic Power Switch** Yes

**LED** on board

Yes

Clear Password Jumper Clear CMOS Button Yes CMOS Battery Holder Yes **DIMM Connectors** Yes

BIOS

**BIOS 32-bit Services** Standard BIOS 32-bit Service Directory Proposal v0.4

**PCI 3.0 Support** 

Full BIOS support for PCI Express through industry standard interfaces.

**ATAPI** 

ATAPI Removable Media Device BIOS Specification Version 1.0.

**BBS** BIOS Boot Specification v1.01.

WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is **WMI Support** 

fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM)

and WBEM specifications.

BIOS Boot Spec 1.01+

Provides more control over how and from what devices the workstation will boot.

**BIOS Power On** 

Users can define a specific date and time for the system to power on.

**ROM Based Computer** Setup Utility (F10)

Review and customize system configuration settings controlled by the BIOS.

System/Emergency ROM

Flash Recovery with

Recovers system BIOS in corrupted Flash ROM.

Video

Saves BIOS settings to USB flash device in human readable file (HpSetup.txt). Replicated Setup

BiosConfigurationUtility.exe utility can then replicate these settings on machines being deployed

without entering Computer Configuration Utility (F10 Setup).

**SMBIOS** System Management BIOS 2.8, for system management information.



## System Technical Specifications

**Boot Control** 

Disables the ability to boot from removable media on supported devices.

**Memory Change Alert Thermal Alert** 

Alerts management console if memory is removed or changed.

Monitors the temperature state within the chassis. Three modes:

• NORMAL - normal temperature ranges.

ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid

shutdown or provide for a smoother system shutdown.

• SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer

without warning before hardware component damage occurs.

Remote ROM Flash **ACPI (Advanced** 

Provides secure, fail-safe ROM image management from a central network console. Allows the system to enter and resume from low power modes (sleep states).

Management Interface)

Configuration and Power Enables an operating system to control system power consumption based on the dynamic workload. Makes it possible to place individual cards and peripherals in a low-power or powered-off state without

affecting other elements of the system.

Supports ACPI 5.0 for full compatibility with 64-bit operating systems.

Ownership Tag

A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.

Remote Wakeup/Remote System administrators can power on, restart, and power off a client computer from a remote location.

Shutdown

Instantly Available PC

(Suspend to RAM - ACPI

sleep state S3)

Allows for very low power consumption with quick resume time.

**Remote System** Installation via F12 (PXE

2.1) (Remote Boot from

Allows a new or existing system to boot over the network and download software, including the operating system.

Server)

**ROM revision levels** 

Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is available through an industry standard interface (SMBIOS and WMI) so that management SW

applications can use and report this information.

System board revision

level

Allows management SW to read revision level of the system board. Revision level is digitally encoded into the HW and cannot be modified. Assesses system health at boot time with selectable levels of testing.

Start-up Diagnostics (Power-on Self-Test)

Auto Setup when new hardware installed

System automatically detects addition of new hardware.

**Keyboard-less Operation** The system can be booted without a keyboard.

Localized ROM Setup

Common BIOS image supports System Configuration Utility (F10 Setup) menus in 14 languages with

local keyboard mappings.

Asset Tag

The user or MIS to set a unique tag string in non-volatile memory.

Per-slot Control **Adaptive Cooling Pre-boot Diagnostics**  Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. Control parameters are set according to detected hardware configuration for optimal acoustics.

(Pre-video) critical errors are reported via beeps and blinks on the power LED.

**Industry Standard Specification Support Industry Standard** 

**UEFI Specification** 2.5

Revision

Revision Supported by the BIOS

**ACPI** Advanced Configuration and Power Management Interface, Version 5.0 ATA (IDE) AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b **CD Boot** "El Torito" Bootable CD-ROM Format Specification Version 1.0

- Enhanced Disk Drive Specification Version 1.1 **EDD** 

- BIOS Enhanced Disk Drive Specification Version 3.0

**EHCI** Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0

PCI PCI Local Bus Specification, Revision 2.3



## **System Technical Specifications**

PCI Power Management Specification, Revision 1.1

PCI Firmware Specification, Revision 3.0, Draft .7

PCI Express PCI Express Base Specification, Revision 2.0

PCI Express Base Specification, Revision 3.0

PMM POST Memory Manager Specification, Version 1.01

SATA Serial ATA Specification, Revision 1.0a

Serial ATA 3 Gb/s: Serial ATA Specification, Revision 2.5 Serial ATA 6 Gb/s: Serial ATA Specification, Revision 3.0

SPD PC SDRAM Serial Presence Detect (SPD) Specification, Revision 1.2B

TPM Trusted Platform Module (TPM) 2.0 (Infineon SLB 9670)

Common Criteria EAL4+ Certified

Convertible to FIPS 140-2 Certified mode through firmware v7.80

TCG TPM Certified products list:

http://www.trustedcomputinggroup.org/certification/tpm-certified-products/

UHCI Universal Host Controller Interface Design Guide, Revision 1.1

USB Universal Serial Bus Revision 1.1 Specification

Universal Serial Bus Revision 2.0 Specification Universal Serial Bus Revision 3.1 G1 Specification Universal Serial Bus Revision 3.1 G2 Specification

SMBIOS System Management BIOS Reference Specification, Version 2.8

External BIOS simulator found at: http://h20464.www2.hp.com/index.html

## **Social and Environmental Responsibility**

**Eco-Label Certifications &** This product has received or is in the process of being certified to the following approvals and may be **Declarations** labeled with one or more of these marks:

- ENERGY STAR® (energy-saving features available on selected configurations-Windows only)
- US Federal Energy Management Program (FEMP)
- China Energy Conservation Program
- The ECO declaration (TED)

The Z6 G4 is registered EPEAT® Gold in the US and Canada. EPEAT® registration varies by country. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3<sup>rd</sup> party option store for solar generator accessories at http://www.hp.com/go/options

The battery in this product complies with EU Directive 2006/66/EC

Battery mass: 3q

Battery type: Lithium Metal

The battery in this product does not contain:

- Mercury greater than 5ppm by weight
- Cadmium greater than 10ppm by weight
- Lead greater than 40ppm by weight

**Restricted Material Usage** This product meets the material restrictions specified in HP's General Specification for the Environment.

HP Inc. is committed to compliance with all applicable environmental laws and regulations, including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to exceed compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis



**Batteries** 

## System Technical Specifications

**Low Halogen Statement** This product is low-halogen except for power cords, external cables and peripherals. Service parts obtained after purchase may not be low-halogen.

## and Recycling

**End-of-Life Management** HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. This product is greater than 90% recyclable by weight when properly disposed of at end of life. For more information about HP's commitment to the environment:

## **HP Inc. Corporate Environmental** Information

Sustainability Report

#### Eco-label certifications:

http://www.hp.com/hpinfo/globalcitizenship/environment/productdesign/ecolabels.html

#### ISO 14001 certificate:

http://www.hp.com/hpinfo/globalcitizenship/environment/operations/envmanagement.html

#### **Additional Information**

- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. Product Disassembly Instructions
- Plastic parts weighing over 25 grams used in the product are marked per ISO 11469 and IS01043.

#### **Packaging**

HP Workstation product packaging meets the HP's General Specification for the Environment

- Does not contain restricted substances listed in HP Standard 011-1 General Specification for the Environment
- Does not contain ozone-depleting substances (ODS)
- Does not contain heavy metals (lead, mercury, cadmium or hexavalent chromium) in excess of 100 ppm sum total for all heavy metals listed
- Maximizes the use of post-consumer recycled content materials in packaging materials
- All packaging material is recyclable
- All packaging material is designed for ease of disassembly
- Reduced size and weight of packages to improve transportation fuel efficiency
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards formatting

## **Packaging Materials** Internal **External**

Cushions and plastic bags made of low density polyethylene (LDPE).

Outer carton, accessories carton, and insert made of corrugated paper board.

## Manageability

**Industry Standard** Specifications

This product meets the following industry standard specifications for manageability functionality:

DASH 1.1 (via Intel® LAN on motherboard)

Intel® Active Management Intel® Active Management Technology (AMT) 11.20 Technology (AMT)

> An advanced set of remote management features and functionality providing IT administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 11.20 includes the following advanced management functions:

Power Management (on, off, reset, graceful shutdown, sleep and hibernate)



## System Technical Specifications

- Support in Max Power Savings (Shutdown and Hibernate Modes)
- Hardware Inventory (includes BIOS and firmware revisions)
- Hardware Alerting
- Agent Presence
- System Defense Filters
- Serial Over LAN (SOL)
- USB Redirect (Media Redirection)
- ME Wake-on-LAN (WOL), even with Maximum Power Savings Enabled
- DASH 1.1 compliance
- IPv6 Support
- Fast Call for Help a client inside or outside the firewall may initiate a call for help via BIOS screen, periodic connections, or alert triggered connection
- Remote Scheduled Maintenance pre-schedule when the system connects to the IT or service provider console for maintenance.
- Remote Alerts automatically alert IT or service provider if issues arise
- Access Monitor Provides oversight into Intel® AMT actions to support security requirements
- PC Alarm Clock
- Microsoft NAP Support
- Host Base set-up and configuration
- Management Engine (ME) firmware roll back
- Local Time Sync to UTC
- Remote Memory Dump Command Creates memory dump for debug

**Intel® vPro™ Technology** The HP Z6 G4 Workstation supports Intel® vPro™ technology when configured as outlined below:

- Intel® Xeon® processor Scalable Family
- Intel® C622 chipset
- Intel® I219LM GbE LAN

### Remote Manageability Software Solutions

The HP Z6 G4 Workstation is supported on the following remote manageability software consoles:

- LANDesk Management Suite (HP recommended solution)
- Microsoft System Center Configuration Manager

System Software Manager Service, Support, and Warranty For questions or support for manageability needs, please visit http://www.hp.com/go/easydeploy For questions or support for SSM, please visit: http://www.hp.com/go/ssm

On-site Warranty and Service (Note 1): Three-years, limited warranty and service offering delivers on-site, next business-day (Note 2) service for parts and labor and includes free telephone support (Note 3) 8am - 5pm. Global coverage (Note 2) ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering. 24/7 operation will not void the HP warranty.

**NOTE 1:** Terms and conditions may vary by country. Certain restrictions and exclusions apply. **NOTE 2:** On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

**NOTE 3:** Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries.

HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/lookuptool. Additional HP Care Pack Services



## **System Technical Specifications**

Product Change Notification information by product is available at: http://www.hp.com/hps/carepack. Service levels and response times for HP Care Packs may vary depending on your geographic location.

- Program to proactively communicate Product Change Notifications (PCNs) and Customer Advisories by email to customers, based on a user-defined profile.
- PCNs provide advance notification of hardware and software changes to be implemented in the factory providing time to plan for transition.
- Customer Advisories provide concise, effective problem resolution, greatly reducing the need to call technical support.



## Stable & Consistent Offerings

As part of its commitment to hardware, software, and solution innovation, HP is proud to introduce this breakthrough platform configuration stability to HP Workstation customers. HP Stable & Consistent Offerings are built on the foundation of a carefully chosen set of hardware and software designed and tested to work with all HP Z Workstation platforms through their end of life. These components and their corresponding HP Workstation platform compatibility are outlined in this section.

HP Stable & Consistent Offerings are available worldwide to all HP Workstation customers-no special programs, no additional cost-no kidding. Simply select your hardware and software components when you customize your HP Workstation and be assured that you'll be able to buy that same configuration throughout the lifecycle of the product.

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Product #	Offering
1XM44AA	Intel® Xeon® Gold 6128 processor
1XM49AA	Intel® Xeon® Silver 4114 processor
1XM51AA	Intel® Xeon® Silver 4108 processor

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Product #	
LQ037AA	

## Offering

1TB SATA 7200 RPM

## Graphics

# **Product #** 2TF08AA

### Offering

AMD Radeon™ Pro WX 3100 4GB Graphics

## Memory

Product #	Offering
TBD	TBD

## Optical and Removable Storage

Product #	Offering
TBD	TBD
TBD	TBD



## **Technical Specifications - Processors**

Intel® Xeon® Platinum 8180 processor

Intel® Xeon® Platinum 8160 processor

Intel® Xeon® Gold 6152 processor

Intel® Xeon® Gold 6154 processor

Intel® Xeon® Gold 6148 processor

Intel® Xeon® Gold 6146 processor

Intel® Xeon® Gold 6144 processor

Intel® Xeon® Gold 6142 processor

Intel® Xeon® Gold 6140 processor

Intel® Xeon® Gold 6138 processor

Intel® Xeon® Gold 6136 processor

Intel® Xeon® Gold 6134 processor

Intel® Xeon® Gold 6132 processor

Intel® Xeon® Gold 6130 processor

Intel® Xeon® Gold 6128 processor

Intel® Xeon® Gold 5120 processor

Intel® Xeon® Gold 5118 processor

Intel® Xeon® Gold 5115 processor

Intel® Xeon® Gold 5122 processor

Intel® Xeon® Silver 4116 processor

Intel® Xeon® Silver 4114 processor

Intel® Xeon® Silver 4112 processor

Intel® Xeon® Silver 4110 processor

Intel® Xeon® Silver 4108 processor

Intel® Xeon® Bronze 3106 processor

Intel® Xeon® Bronze 3104 processor

3.5 in; 8.9 cm

2.0ms

**Technical Specifications - Hard Drives** 

## STORAGE/HARD DRIVES

**HP SAS (Serial Attached** SCSI) Hard Drives for HP **Workstations** 

**HP 300GB SAS 15K SFF** 

HDD

Capacity 300GB Height 5.9 in: 15 cm Width **Media Diameter** 

12Gb/s SAS Interface

**Synchronous Transfer** 

Rate (Maximum)

128MB

Up to 1200 MB/s (SAS single port)

**Buffer Average** 

**Seek Time** (typical reads, includes controller

overhead, including

**Rotational Speed** 

settling)

15K rpm

**Operating Temperature** 41° to 131° F (5° to 55° C)

**HP 1.2TB SAS 15K SFF** HDD

1.2TB Capacity

Height 0.6 in; 1.53 cm

Width **Media Diameter** 2.5 in; 6.36 cm **Physical Size** 2.75 in; 6.99 cm

Interface SAS 6Gb/s Up to 600MB/s **Synchronous Transfer** 

Rate (Maximum)

**Buffer 64MB** 

**Seek Time** (typical reads, Single Track 0.18ms (max) includes controller Average 3.5ms overhead, including **Full Stroke** 7.17ms settling)



## **Technical Specifications - Hard Drives**

SATA (Serial ATA) Hard
Drives for HP
Workstations

500GB SATA 7200 rpm 6Gb/s 3.5" HDD

Capacity 500GB Height 1 in: 2.54 cm Width

**Media Diameter** 3.5 in; 8.9 cm **Physical Size** 4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

**Synchronous Transfer** 

Rate (Maximum)

Up to 600MB/s

**Buffer 16MB** 

**Seek Time** (typical reads. Single Track 2 ms includes controller **Average** 11 ms overhead, including **Full Stroke** 21 ms settling)

**Rotational Speed** 7,200 rpm **Logical Blocks** 976,773,168

**Operating Temperature** 41° to 131° F (5° to 55° C)

1TB SATA 7200 rpm 6Gb/s 3.5" HDD

1TB Capacity

Height 1 in; 2.54 cm

Width **Media Diameter** 3.5 in; 8.9 cm

**Physical Size** 4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

**Synchronous Transfer** 

Rate (Maximum)

Up to 600 MB/s

**Buffer** 64MB Cache Adaptive

**Seek Time** (typical reads, **Single Track** 2 ms includes controller Average 11 ms overhead, including **Full Stroke** 21 ms settling)

**Rotational Speed** 7,200 rpm

**Operating Temperature** 41° to 131° F (5° to 55° C)

2.0TB SATA 7200 rpm 6Gb/s 3.5" HDD

Capacity 2.0TB Height 1 in; 2.54 cm

Width **Media Diameter** 3.5 in; 8.9 cm **Physical Size** 4 in; 10.17 cm

Interface Serial ATA (6.0 Gb/s), NCQ Enabled

**Synchronous Transfer** Up to 600 MB/s

Rate (Maximum)

**Buffer** 64MB

**Seek Time** (typical reads. **Single Track** 1.0 ms includes controller Average 11 ms overhead, including **Full Stroke** 18 ms settling)

**Rotational Speed** 7,200 rpm **Logical Blocks** 3,907,029,168

**Operating Temperature** 41° to 131° F (5° to 55° C)

## **Technical Specifications - Hard Drives**

3.0TB SATA 7200 rpm 6Gb/s 3.5" HDD Capacity 3.0TB Height 1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm
Physical Size 4.0 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

**Synchronous Transfer** Up to 6.0 Gb/s

Rate (Maximum)

Buffer 64MB

Seek Time (typical reads, includes controller overhead, including settling)Single Track overhead, one of the single track overhead, including settling)0.6 ms4 Verage overhead, including settling)11 msFull Stroke overhead, including settlingNot Specified

**Rotational Speed** 7,200 rpm

**Operating Temperature** 41° to 140° F (5° to 60° C)

1TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class) Capacity 1TB
Protocol SATA
Form Factor 3.5"
Controller AHCI
Reliability (MTBF) 2.0M hours
Rated Power On Hours 8760/yr
Annualized Failure Rate <0.62%

(based on Rated POH)

Rated for 24/7/365 YES

operation

Physical Size (Height)1 in; 2.54 cmPhysical Size (Width)4 in; 10.17 cmMedia Diameter3.5 in; 8.9 cm

Interface Serial ATA (6Gb/s), NCQ enabled

Up to 600MB/s

**Synchronous Transfer** 

Rate (Maximum)

Buffer 128MB

Seek Time (typical reads,<br/>includes controller<br/>overhead, including<br/>settling)Single Track<br/>Average0.32msAverage<br/>Full Stroke7.45ms14.2ms

**Operating Temperature** 41° to 140° F (5° to 60° C)

**Performance** Sequential Read up to 226MB/s

**Sequential Write** up to 226MB/s

**Enterprise Class Features** High Reliability



### **Technical Specifications - Hard Drives**

4TB SATA 7200 rpm
6Gb/s 3.5" HDD
(Enterprise Class)

Capacity 4TB

Height 0.275 in; 0.7 cm

**Media Diameter** Width 2.5 in; 6.36 cm **Physical Size** 2.75 in; 6.99 cm

Up to 600MB/s

Interface Serial ATA (6Gb/s), NCQ enabled

**Synchronous Transfer** 

Rate (Maximum)

Buffer 128MB

**Seek Time** (typical reads, **Single Track** 0.7ms includes controller **Average** 8.5ms overhead, including **Full Stroke** 15.7ms

settling)

Rotational Speed 7,200 rpm

**Operating Temperature** 32° to 140° F (0° to 60° C)

#### **500GB SATA 7.2K SED SFF HDD**

Capacity 500GB

Height 0.275 in: 0.7 cm

Width **Media Diameter** 2.5 in; 6.36 cm **Physical Size** 2.75 in; 6.99 cm

1ms

4.2ms

25ms (typical)

Interface Serial ATA (6Gb/s) **Synchronous Transfer** Up to 600MB/s

Rate (Maximum)

**32MB** 

**Seek Time** (typical reads, **Single Track** includes controller Average overhead, including **Full Stroke** 

settling)

**Rotational Speed** 

**Operating Temperature** 32° to 140° F (0° to 60° C)

7,200 rpm



### **Technical Specifications - Hard Drives**

SATA SSDs for	HP
Workstations	

HP 256GB SATA 6Gb/s SSD

Capacity 256GB **Protocol** SATA **Form Factor** 2.5" Controller **AHCI NAND Type** 3D TLC

**Endurance** 192TBW (TB Written)

Reliability (MTTF) 1.5M hours Physical Size (Height) 0.28 in; 0.7 cm Physical Size (Width) 2.5 in: 6.36 cm Interface SATA 6Gb/s **Synchronous Transfer** Up to 600MB/s

Rate (Maximum)

**Operating Temperature** 

32° to 158° F (0° to 70° C)

**Performance** 

**Sequential Read** 530MB/s (max) **Sequential Write** 500MB/s (max) **Random Read** 55K IOPS (max) **Random Write** 83K IOPS (max)

#### HP 256GB SATA 6Gb/s SED Opal 2 SSD

Capacity 256GB **Protocol SATA Form Factor** 2.5" Controller **AHCI NAND Type** 3D TLC

**Endurance** 192TBW (TB Written)

Reliability (MTTF) 1.5M hours Physical Size (Height) 0.28 in: 0.7 cm Physical Size (Width) 2.5 in; 6.36 cm Interface 6Gb/s SATA

**Synchronous Transfer** Rate (Maximum)

Up to 550MB/s (Sequential Read)

**Operating Temperature** 

32° to 158° F (0° to 70° C)

**Performance** 

**Sequential Read** 530MB/s **Sequential Write** 500 MB/s **Random Read 55K IOPS Random Write 83K IOPS** 

**Self-Encrypting Drive** 

Support

OPAL 2

#### HP 512GB SATA 6Gb/s SSD

Capacity 512GB **Protocol** SATA Form Factor 2.5" Controller **AHCI NAND Type** 3D TLC

**Endurance** 388TBW (TB Written)

**Reliability (MTTF)** 1.5M hours Physical Size (Height) 0.28 in; 0.7 cm

### **Technical Specifications - Hard Drives**

Physical Size (Width) 2.5 in; 6.36 cm Interface SATA 6Gb/s

**Synchronous Transfer** 

**Operating Temperature** 

Rate (Maximum)

32° to 158° F (0° to 70° C)

**Performance** 

**Sequential Read** 530 MB/s **Sequential Write** 500 MB/s **Random Read 95K IOPS** 

Up to 550MB/s (Sequential Read)

**Random Write** 

**83K IOPS** 

**HP 512GB SATA SED SSD** 

512GB Capacity **Protocol** SATA **Form Factor** 2.5" Controller AHCI **NAND Type** 3D TLC

**Endurance** 388TBW (TB Written)

Reliability (MTTF) 1.5M hours Physical Size (Height) 0.28 in; 0.7 cm Physical Size (Width) 2.5 in: 6.36 cm Interface SATA 6Gb/s **Synchronous Transfer** Up to 600MB/s

Rate (Maximum)

**Operating Temperature** 

32° to 158° F (0° to 70° C)

**Performance Sequential Read** 530 MB/s

Sequential Write 500 MB/s **Random Read** 95K IOPS **Random Write 83K IOPS** 

**Self-Encrypting Drive** 

Support

OPAL 1 and 2

**HP 1TB SATA 6Gb/s SSD** 

Capacity 1TB Protocol **SATA** 2.5" **Form Factor** Controller **AHCI NAND Type** 3D TLC

**Endurance** 400TBW (TB Written)

Reliability (MTTF) 1.5M hours Physical Size (Height) 0.28 in: 0.7 cm Physical Size (Width) 2.5 in; 6.36 cm Interface SATA 6Gb/s

**Synchronous Transfer** Rate (Maximum)

Up to 550MB/s (Sequential Read)

**Operating Temperature** 32° to 158° F (0° to 70° C)

**Performance** Sequential Read 530 MB/s

**Sequential Write** 500 MB/s **Random Read 95K IOPS Random Write 83K IOPS** 



### **Technical Specifications - Hard Drives**

ti	ons - Hard Drives				
	HP 2TB SATA 6Gb/s SSD	Capacity	2TB		
		Protocol	SATA		
		Form Factor	2.5"		
		Controller	AHCI		
		NAND Type	3D TLC		
		Endurance	400TBW (TB Written)		
		Reliability (MTTF)	1.5M hours		
		Physical Size (Height)	0.28 in; 0.7 cm		
		Physical Size (Width)	2.5 in; 6.36 cm		
		Interface	SATA 6Gb/s		
		Synchronous Transfer Rate (Maximum)	Up to 550MB/s (Sequential Read)		
		Operating Temperature	32° to 158° F (0° to 70° C)		
		Performance	Sequential Read	530 MB/s	
			Sequential Write	500 MB/s	
			Random Read	95K IOPS	
			Random Write	83K IOPS	
	<b>HP Enterprise Class</b>	Capacity	240GB		
	240GB SATA SSD	Protocol	SATA		
		Form Factor	2.5"		
		Controller	AHCI		
		NAND Type	3D TLC		
		Endurance	2,200TBW (TB Written)		
		Reliability (MTTF)	2.0M hours		
		Physical Size (Height)	0.28 in; 0.7 cm		
		Physical Size (Width)	2.5 in; 6.36 cm		
		Interface 6Gb/s SATA			
		Synchronous Transfer Rate (Maximum)	Up to 600MB/s		
		Operating Temperature	32° to 158° F (0° to 70° C)		
		Performance	Sequential Read	540 MB/s	
			Sequential Write	310 MB/s	
			Random Read	93K IOPS	
		Futurais Class Footons	Random Write	48K IOPS	
		Enterprise Class Features	Power Loss Protection End-to-End Data Protec	tion	
	HP Enterprise Class 480GB SATA SSD	Capacity	480GB		
		Protocol	SATA		
		Form Factor	2.5"		
		Controller	AHCI		
		NAND Type	3D TLC		
		Endurance	4,400TBW (TB Written)		
		Reliability (MTTF)	2.0M hours		

Physical Size (Height)

0.28 in; 0.7 cm

### **Technical Specifications - Hard Drives**

Physical Size (Width)	2.5 in; 6.36 cm
Interface	6Gb/s SATA
Synchronous Transfer	Up to 600MB/s
Rate (Maximum)	

**Operating Temperature** 

32° to 158° F (0° to 70° C)

**Performance** 

**Sequential Read** 540 MB/s **Sequential Write** 460 MB/s **Random Read 93K IOPS Random Write 74K IOPS** 

**Enterprise Class Features** High Endurance NAND **Power Loss Protection End-to-End Data Protection** 

**PCIe SSDs for HP** Workstations

**HP Z Turbo Drive G2 256GB SSD** 

Capacity 256GB **Protocol** PCIe **Form Factor** M.2 Controller NVMe MLC **NAND Type Endurance** 150TB Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

**Operating Temperature** 

32° to 158° F (0° to 70° C)

Performance

**Sequential Read** 2800 MB/s **Sequential Write** 1100 MB/s **Random Read 250K IOPS Random Write 180K IOPS** 

**HP Z Turbo Drive G2 512GB SSD** 

Capacity 512GB **Protocol** PCIe **Form Factor** M.2 Controller NVMe **NAND Type** 3D MLC **Endurance** 300TB Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

**Operating Temperature** 

32° to 158° F (0° to 70° C)

Performance **Sequential Read Sequential Write Random Read** 

**260K IOPS Random Write 260K IOPS** 

2800 MB/s

1600 MB/s

HP Z Turbo Drive G2 1TB Capacity SSD

1TB **Protocol PCIe Form Factor** M.2 Controller NVMe

### **Technical Specifications - Hard Drives**

NAND Type 3 D MLC
Endurance 600TB
Reliability (MTTF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

**Operating Temperature** 32° to 158° F (0° to 70° C)

**Performance** Sequential Read 3000 MB/s

Sequential Write1700 MB/sRandom Read360K IOPSRandom Write330K IOPS



### **Technical Specifications - Hard Drives**

HP Z Turbo Drive Quad Pro 2x256GB PCIe SSD **Capacity** 512GB **Protocol** PCIe

**Form Factor** PCIe Card, Full Height PCIe Slot

ControllerNVMeNAND TypeMLCEndurance150TBReliability (MTBF)1.5M hours

**Interface** PCIe Gen3 x4 architecture **Operating Temperature** 32° to 158° F (0° to 70° C)

**Performance** Sequential Read 2800 MB/s

Sequential Write1100 MB/sRandom Read250K IOPSRandom Write180K IOPS

HP Z Turbo Drive Quad Pro 2x512GB PCIe SSD Capacity 1TB Protocol PCIe

**Form Factor** PCIe Card, Full Height PCIe Slot

ControllerNVMeNAND Type3D MLCEndurance300TBReliability (MTBF)1.5M hours

Interface PCIe Gen3 x4 architecture
Operating Temperature 32° to 158° F (0° to 70° C)

**Performance Sequential Read** 2800 MB/s

Sequential Write1600 MB/sRandom Read260 K IOPSRandom Write260K IOPS

HP Z Turbo Drive Quad Pro 2x1TB PCIe SSD Capacity 2TB Protocol PCIe

**Form Factor** PCIe Card, Full Height PCIe Slot

ControllerNVMeNAND Type3D MLCEndurance600TB

Interface PCI Express 3.0 x4 electrical x4 physical

**Operating Temperature** 32° to 158° F (0° to 70° C)

Performance Sequential Read

Sequential Read 3000 MB/s
Sequential Write 1700 MB/s
Random Read 360 K IOPS

**Random Write** 330K IOPS

HP Z Turbo Drive G2 256GB SED SSD Capacity 256GB Protocol PCIe

### **Technical Specifications - Hard Drives**

**Form Factor** M.2 Controller NVMe **NAND Type** MLC

**Endurance** 150TBW (TB Written)

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

**Operating Temperature** 32° to 158° F (0° to 70° C)

Performance **Sequential Read** 

2800 MB/s **Sequential Write** 1100 MB/s **Random Read 250K IOPS Random Write 180K IOPS** 

**Self-Encrypting Drive** 

Support

OPAL 2

#### **HP Z Turbo Drive G2** 512GB SED SSD

Capacity 512GB **PCIe Protocol Form Factor** M.2 Controller NVMe **NAND Type** MLC

300TBW (TB Written) **Endurance** 

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

32° to 158° F (0° to 70° C) **Operating Temperature** 

**Performance Sequential Read** 2800 MB/s

> **Sequential Write** 1600 MB/s **Random Read 260K IOPS Random Write 260K IOPS**

**Self-Encrypting Drive** OPAL 2

Support

#### **HP Z Turbo Drive Quad Pro Capacity** 2x1TB PCIe SSD

2TB **Protocol** PCIe

**Form Factor** PCIe Card, Full Height PCIe Slot

Controller NVMe **NAND Type** 3D MLC **Endurance** 600TB

Interface PCI Express 3.0 x4 electrical x4 physical

**Operating Temperature** 32° to 158° F (0° to 70° C)

**Performance Sequential Read** 3000 MB/s

> Sequential Write 1700 MB/s **Random Read 360K IOPS Random Write 330K IOPS**

**HP Z Turbo Drive G2** 256GB TLC SSD

Capacity 256GB **Protocol PCIe Form Factor** M.2

### **Technical Specifications - Hard Drives**

Controller NVMe NAND Type 3D TLC

**Endurance** 75TBW (TB Written)

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

**Operating Temperature** 32° to 158° F (0° to 70° C)

**Performance Sequential Read** 2800 MB/s

**Sequential Write** 320 MB/s (1100 MB/s

max/Turbo)

**Random Read** 250K IOPS **Random Write** 180K IOPS

HP Z Turbo Drive G2 512GB TLC SSD Capacity512GBProtocolPCIeForm FactorM.2ControllerNVMeNAND Type3D TLC

**Endurance** 150TBW (TB Written)

**Reliability** (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

**Operating Temperature** 32° to 158° F (0° to 70° C)

**Performance** Sequential Read 2800 MB/s

**Sequential Write** 660 MB/s (1600 MB/s

max/Turbo)

**Random Read** 260K IOPS **Random Write** 260K IOPS

HP Z Turbo Drive G2 1TB TLC SSD

 Capacity
 1TB

 Protocol
 PCle

 Form Factor
 M.2

 Controller
 NVMe

 NAND Type
 3D TLC

**Endurance** 300TBW (TB Written)

**Reliability** (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

**Operating Temperature** 32° to 158° F (0° to 70° C)

**Performance** Sequential Read 3000 MB/s

**Sequential Write** 1150 MB/s (1700 MB/s

max/Turbo)

**Random Read** 360K IOPS **Random Write** 330K IOPS

HP Z Turbo Drive Quad Pro Capacity

256GB SSD module

256GB (one M.2 PCIe NVMe module)

Interface PCI Express 3.0 x4 electrical x4 physical

**Operating Temperature** 32° to 158° F (0° to 70° C)

**Technical Specifications - Hard Drives** 

**HP Z Turbo Drive Quad Pro Capacity** 512GB (one M.2 PCIe NVMe module)

512GB SSD module

Interface PCI Express 3.0 x4 electrical x4 physical

**Operating Temperature** 32° to 158° F (0° to 70° C)

**HPZ Turbo Drive Quad Pro Capacity** 

**1TB SSD module** 

1TB (one M.2 PCIe NVMe module)

Interface PCI Express 3.0 x4 electrical x4 physical

**Operating Temperature** 32° to 158° F (0° to 70° C)

Intel® 905p Series AIC PCIe SSD

Intel® 905p Series AIC 280GB PCIe SSD

Capacity 280GB Protocol PCIe

Form Factor PCIe Card, Half Height

**Controller** NVMe **NVM Type** 3DXPoint

**Endurance** 5.11 PBW (PB Written)

**Reliability** (MTBF) 1.6M hours

**Operating Temperature** 32° to 185° F (0° to 85° C)

Performance Sequential Read 2730 MB/s
Sequential Write 2280 MB/s

Random Read 587K IOPS Random Write 559K IOPS

Intel® 905p Series AIC 480GB PCIe SSD Capacity 480TB Protocol PCIe

**Form Factor** PCIe Card, Half Height

Controller NVMe NVM Type 3DXPoint

**Endurance** 8.76 PBW (PB Written)

**Reliability** (MTBF) 1.6M hours

Operating Temperature 32° to 185° F (0° to 85° C)

**Performance Sequential Read** 27100 MB/s

Sequential Write2280 MB/sRandom Read582K IOPSRandom Write561K IOPS

### **Technical Specifications - Hard Drive Controllers**

### HARD DRIVE CONTROLLERS

Microsemi PCI Bus SmartHBA2100-4i4e SAS RAID Levels

Controller

**PCI Bus** 8 lanes, PCI Express 3.0

**RAID Levels** Offers Integrated RAID (0, 1, and 10) **PCI Data Burst Transfer** Half Duplex x8, PCIe, 8000 MB/s

Rate

SAS Bandwidth Half Duplex 1200 MB/s per lane

PCI Card Type 3.3V Add-in Card PCI Voltage 12 V ± 10%

**PCI Power** 9.8W typical, Airflow min 200 LFM

**Bracket** Full height and low profile **Certification Level** PCI Express 3.0 compliant

SAS ProcessorMicrosemi SmartIOC 2100 SAS IO ControllerInternal ConnectorsOne x4 internal mini-SASHD (SFF-8643)External ConnectorsOne x4 external mini-SASHD (SFF-8644)

Maximum Number of SCSI 256 Non-RAID SAS/SATA devices

**Devices** 

**LED Indicators** Connector for Drive Activity Light



### **Technical Specifications - Graphics**

#### **GRAPHICS**

NVIDIA® Quadro® P400 1st GFX 2GB Graphics

**Form Factor** Dimensions: 2.713" H x 5.7" L

Single Slot, Low Profile

Cooling: Active Weight: 129 grams

**Graphics Controller** NVIDIA® Quadro® P400 Graphics Card

GP107-825 GPU

256 NVIDIA® CUDA® cores Max Power: 30 Watts

PCI Express 3.0 x16 **Bus Type** 

Memory Size: 2 GB GDDR5, 2000 MHz

Memory Interface: 64-bit Memory Bandwidth: 32 GB/s

**3mDP Outputs Connectors** 

**Maximum Resolution** DisplayPort™ 1.4:

> - up to 3x 5120 x 2880 x 24 bpp @ 60Hz supports Multi-Stream Transport (MST)

10-bit internal display processing pipeline **Image Quality Features** 

10-bit scan-out support

**Display Output** 3 mDP Connectors

Shading Architecture

Full Microsoft DirectX® 12 Shader Model 5.1 **Supported Graphics APIs** 

OpenGL® 4.5 DirectX® 12 Vulkan™ 1.0

API support includes:

CUDA C, CUDA C++, DirectCompute, OpenCL™

**Available Graphics** 

**Drivers** 

Microsoft Windows 10 Microsoft Windows 8.1 Microsoft Windows 7

Linux®

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

**Notes** 

NVIDIA® Quadro® P600 1st Form Factor

**GFX 2GB Graphics** 

Dimensions: 2.713" H x 5.7" L Single Slot, Low Profile

Cooling: Active Weight: 129 grams

**Graphics Controller** NVIDIA® Quadro® P600 Graphics Card

GP107-850 GPU

384 NVIDIA® CUDA® cores Max Power: 40 Watts

**Bus Type** PCI Express 3.0 x16

#### Technical Specifications - Graphics

Memory Size: 2 GB GDDR5, 2000 MHz

> Memory Interface: 128-bit Memory Bandwidth: 64 GB/s

Connectors 4mDP Outputs **Maximum Resolution** 

DisplayPort™ 1.4:

- up to 4x 5120 x 2880 x 24 bpp @ 60Hz - supports Multi-Stream Transport (MST)

**Image Quality Features** 10-bit internal display processing pipeline

10-bit scan-out support

**Display Output** 4 mDP Connectors

Full Microsoft DirectX® 12 Shader Model 5.1 **Shading Architecture** 

Supported Graphics APIs OpenGL® 4.5

DirectX® 12 Vulkan™ 1.0

API support includes:

CUDA C, CUDA C++, DirectCompute, OpenCL™

**Available Graphics** 

**Drivers** 

Microsoft Windows 10 Microsoft Windows 8.1 Microsoft Windows 7

Linux®

HP qualified drivers may be preloaded or available from the HP support

http://welcome.hp.com/country/us/en/support.html

Notes

#### AMD FirePro™ W2100 **2GB Graphics**

**Form Factor** 

Low Profile, half length (full-height bracket included)

**Graphics Controller** 

AMD FirePro™ W2100 professional graphics based on Oland GPU. GPU: 320 Stream Processors organized into 5 Compute Units

**GPU Frequency: 630Mhz** 

Power: 26W Cooling: Active

**Bus Type** PCI Express® x8, Generation 3.0

Memory 2GB DDR3 memory

Memory Bandwidth: up to 28.8 GB/s

Memory Width: 128 bit

**Connectors** 2x Display Port™ 1.2 connectors

> Factory Configured: No video cable adapter included After market option kit: No video cable adapter included

Additional DisplayPort™-to-VGA or DisplayPort™-to-DVI adapters are

available as Factory Configuration or Option Kit accessories.

**Maximum Resolution** DisplayPort™ 1.2:

- up to 4096x2160 x 24 bpp @ 60Hz



#### **Technical Specifications - Graphics**

Dual Link DVI(I) (requires adapter cable): - up to 2560 x 1600 x 32 bpp @ 60Hz

Single Link-DVI(I)(requires adapter cable): - up to 1920 x 1200 x 32 bpp @ 60Hz

VGA (requires adapter cable):

- up to 1920 x 1200 x 32 bpp @ 60Hz

**Image Quality Features** Advanced support for 8-bit, 10-bit, and 16-bit per RGB color component.

High bandwidth scaler for high quality up and downscaling.

**Display Output** 2 x DisplayPort™ 1.2a

Maximum number of displays: 2

**Shading Architecture** Shader Model 5.0

Supported Graphics APIs OpenCL™ 1.2, DirectX® 11.2/12, OpenGL® 4.4

OpenGL® 4.4 support with driver release 14.301.xxx

OpenCL™ 1.2 conformance expected with drive release 14.301.xxx

**Available Graphics** 

**Drivers** 

Windows10 (64-bit)
Windows 8.1 (64-bit)

Windows 7 (64-bit)

Linux®

HP qualified drivers may be preloaded or available from the HP support

Web site

http://welcome.hp.com/country/us/en/support.html

**Notes** Depending on the card model, native DisplayPort™ connectors and/or

certified DisplayPort<sup>™</sup> active or passive adapters to convert your monitor's native input to your card's DisplayPort<sup>™</sup> or Mini-DisplayPort<sup>™</sup> connector(s)

may be required. See www.amd.com/FirePro™ for details.

NVIDIA® Quadro® P1000 1st GFX 4GB Graphics **Form Factor** Dimensions:2.713" H x 5.7" L

Single Slot, Low Profile

Cooling: Active Weight: 129 grams

Graphics Controller NVIDIA® Quadro® P1000 Graphics Card

GP107-860 GPU

640 NVIDIA® CUDA® cores Max Power: 47 Watts PCI Express 3.0 x16

**Bus Type** PCI Express 3.0 x16

Memory Size: 4 GB GDDR5, 2500 MHz

Memory Interface: 128-bit memory interface Memory Bandwidth: 80 GB/s memory bandwidth

**Connectors** 4mDP Outputs **Maximum Resolution** DisplayPort™ 1.4:

### **Technical Specifications - Graphics**

- up to 4x 5120 x 2880 x 24 bpp @ 60Hz

- supports Multi-Stream Transport (MST)

**Image Quality Features** 10-bit internal display processing pipeline

10-bit scan-out support

**Display Output** 4 mDP Connectors

**Shading Architecture** 

Full Microsoft DirectX® 12 Shader Model 5.1

Supported Graphics APIs OpenGL® 4.5 DirectX® 12 Vulkan™ 1.0

API support includes:

CUDA C, CUDA C++, DirectCompute, OpenCL™

**Available Graphics** 

**Drivers** 

Microsoft Windows 10 Microsoft Windows 8.1 Microsoft Windows 7

Linux®

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

**Notes** 

NVIDIA® Ouadro® P2000 1st GFX 5GB Graphics

**Form Factor** 

Dimensions: 4.4"Hx7.9"L

Single Slot Cooling: Active Weight: 260 grams

**Graphics Controller** NVIDIA® Quadro® P2000 Graphics Card

Power: 75 Watts

**Bus Type** PCI Express 3.0 x16 Memory Size: 5GB GDDR5

Memory Bandwidth: 140 GB/s

Memory Width: 160-bit

4x DisplayPort™ 1.4 Connectors

> Factory Configured Option: No adapter included with card After Market Option: No video cable adapter included

Additional DVI to VGA, DisplayPort™ to VGA, DisplayPort™ to DVI, and DisplayPort™ to Dual-Link DVI adapters available as accessories.

**Maximum Resolution** DisplayPort™:

- up to 5120 x 2880 x 24 bpp @ 60Hz

- supports High Bit Rate 2 (HBR2) and Multi-Stream Transport (MST) DP 1.3

& 1.4 ready.

DL-DVI(I) output:

- up to 2560 x 1600 x 32 bpp @ 60 Hz

Single Link-DVI(I) output:

- up to 1920 x 1200 x 32 bpp @ 60Hz

HDMI 2.0 (requires DP to HDMI adapter):

5120 x 2880 x 24 bpp @ 60Hz

### **Technical Specifications - Graphics**

**Image Quality Features** 12-bit internal display pipeline (hardware support for 12-bit scanout on

supported panels, applications and connection)

Stereoscopic 3D display support including NVIDIA® 3D Vision™ technology,

NVIDIA® Mosaic and nView.

**Display Output** Maximum number of displays

- 4 direct attached monitors

Maximum number of monitors across all available Quadro P2000 outputs

is 4.

**Shading Architecture** 

Shader Model 5.1 Supported Graphics APIs

OpenGL® 4.5

DirectX® 12

API support includes:

CUDA C, CUDA C++, DirectCompute 5.0, OpenCL™, Java, Python, and Fortran

software

**Available Graphics** 

**Drivers** 

Microsoft Windows 10

Microsoft Windows 7 Professional 64bit

Linux® - Full OpenGL® implementation, complete with NVIDIA® and ARB

extensions

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

Radeon™ Pro WX 3100 **4GB Graphics** 

**Form Factor** 

Low-Profile Single Slot (6.6" Length)

**Graphics Controller** 

Polaris12 GL

GPU: 512 Stream Processors organized into 8 Compute Units

Power: 50 Watts Cooling: Active

Memory 4GB GDDR5 memory

Memory Bandwidth: 6 Gbps / 96 GB/s

Memory Width: 128 bit

**Connectors** 2x Mini DisplayPort™ 1.4 plus 1x DisplayPort™ 1.4 – HDR ready connectors

with HBR3 and MST support.

Factory Configured: No adapters included

After market option kit: One mDP-to-DP cable adapters included

Additional Mini DisplayPort™-to-DisplayPort™, DisplayPort™-to-VGA or DisplayPort™-to-DVI adapters are available as Factory Configuration or

Option Kit accessories.

**Maximum Resolution** 5K support @ 60Hz

1x single-cable 5K monitor, or 2x dual-cable 5K monitors

3x 4K support @ 60Hz

**Image Quality Features** Advanced support for 8-bit and 10-bit per RGB color component. High

bandwidth scaler for high quality up and downscaling

### **Technical Specifications - Graphics**

**Display Output** 3 full physical DP1.3 HBR3 / DP1.4 HDR outputs

FreeSync support

**GPU Architecture** Polaris

**Supported Graphics APIs** DirectX°12

OpenGL® 4.5 OpenCL™ 2.0 Vulkan™ 1.0

**Available Graphics** 

**Drivers** 

Windows 10 64-bit

(Windows® 7 64-bit available from AMD)

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

#### Notes

- HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.
- 2. AMD PowerTune and AMD ZeroCore Power are technologies offered by certain FirePro™ and Radeon™ Pro products, which are designed to intelligently manage GPU power consumption in response to certain GPU load conditions.
- 3. As of September 2016, certified for DisplayPort™ 1.4 HBR3 and ready for DisplayPort™ 1.4 HDR based on independent verification by DisplayPort™ testing authority. HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.

#### Radeon™ Pro WX 4100 4GB Graphics

Form Factor

Low-Profile Single Slot (6.6" Length)

**Graphics Controller** 

Polaris 11 Baffin GL XT

GPU: 1024 Stream Processors organized into 16 Compute Units

Power: 50 Watts Cooling: Active

**Memory** 4GB GDDR5 memory

Memory Bandwidth: 6 Gbps / 96 GB/s

Memory Width: 128 bit

Connectors 4x Mini DisplayPort™ 1.4 – HDR ready connectors with HBR3 and MST

support.

Factory Configured: Four mDP-to-DP cable adapters included After market option kit: Four mDP-to-DP cable adapters included

Additional DisplayPort™-to-VGA or DisplayPort™-to-DVI adapters are

available as Factory Configuration or Option Kit accessories.



### **Technical Specifications - Graphics**

Maximum Resolution 5K support @ 60Hz

• 1x single-cable 5K monitor, or 2x dual-cable 5K monitors

4x 4K support @ 60Hz

Image Quality Features Advanced support for 8-bit and 10-bit per RGB color component. High

bandwidth scaler for high quality up and downscaling

**Display Output** 4 full physical DP1.3 HBR3 / DP1.4 HDR outputs

FreeSync support

**GPU Architecture** GCN 4th Generation

**Supported Graphics APIs** DirectX°12

OpenGL<sup>®</sup> 4.5 OpenCL<sup>™</sup> 2.0 Vulkan<sup>™</sup> 1.0

**Available Graphics** 

**Drivers** 

Windows 10 64-bit Windows® 7 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

**Notes** 

4. HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.

5. AMD PowerTune and AMD ZeroCore Power are technologies offered by certain FirePro™ and Radeon™ Pro products, which are designed to intelligently manage GPU power consumption in response to certain GPU load conditions.

6. As of September 2016, certified for DisplayPort™ 1.4 HBR3 and ready for DisplayPort™ 1.4 HDR based on independent verification by DisplayPort™ testing authority. HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windows mode content requires operating system support.

NVIDIA® Quadro® P4000 1st GFX 8GB Graphics Form Factor Dimensions: 4.4"H x 9.5"L

Single-slot, full-height

Weight: 475 grams (without extender)

**Graphics Controller** NVIDIA® Quadro® P4000 Graphics Card

GPU: GP104 with 1792 CUDA cores

Power: 120 Watts

**Bus Type** PCI Express 3.0 x16 **Memory** Size: 8GB GDDR5

SIZE: 8GB GDDR5

Memory Randwidth

Memory Bandwidth: 243 GB/s Memory Width: 256-bit



#### **Technical Specifications - Graphics**

**Connectors** 4 x DisplayPort 1.4

3-pin mini-DIN connector via optional bracket

1 x 6-pin auxiliary power connector 4-pin header for stereo signal SYNC connector for Quadro® Sync II

2 x SLI connectors

Factory Configured Option: No video cable adapter included After Market Option: No video cable adapter included

Additional DisplayPort-to-VGA, DisplayPort-to-HDMI, or DisplayPort-to-

DVI adapters are available as accessories

**Maximum Resolution** Dual-link internal TMDS (DVI 1.0):

- up to 2560 x 1600 x 32 bpp @ 60 Hz

Single-link internal TMDS (DVI 1.0): - up to 1920 x 1200 x 32 bpp @ 60 Hz

HDMI<sup>™</sup> 2.0b (requires DP to HDMI adapter): - up to 5120 x 2880 x 24 bpp @ 60Hz

DisplayPort:

- up to 4096 x 2160 x 30 bpp @ 60Hz- up to 2560 x 1600 x 30 bpp @ 120 Hz

- supports High Bit Rate 2 (HBR2) and Multi-Stream Transport (MST)

Using two DP outputs, the P4000 can drive one dual DP input display with

5120 x 2880 x 30 bpp @ 60Hz resolution.

Image Quality Features Advanced support for 8-bit, 10-bit, and 12-bit per RGB color

component.

HDCP 2.2 support over DisplayPort, DVI, and HDMI connectors

NVIDIA 3D Vision™ and other 3D stereo technologies

**NVIDIA Mosaic and nView** 

**Display Output** Maximum number of displays

- 4 direct attached monitors

Maximum number of monitors across all available Quadro P4000 outputs

is 4.

**Shading Architecture** Shader Model 5.1

**Supported Graphics APIs** OpenGL 4.5

DirectX 12 Vulcan 1.0

API support includes:

CUDA C, CUDA C++, DirectCompute 5.0, OpenCL, Java, Python, and Fortran

**Available Graphics** 

**Drivers** 

Microsoft Windows 10 Microsoft Windows 7

Linux - Full OpenGL implementation, complete with NVIDIA and ARB

extensions

HP qualified drivers may be preloaded or available from the HP support

Web site:



### Technical Specifications - Graphics

### Notes

http://welcome.hp.com/country/us/en/support.html

- Quadro P4000 offered as Factory Configured Option does not include a video cable adapter. Video cable adapters must be ordered separately.
- 2. Quadro P4000 offered as an After Market Option does not include video cables. Video cable adapters must be ordered separately.

### **NVIDIA® Quadro®** P5000 1st GFX 16GB **Graphics**

**Form Factor** 

Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 815 grams / 1.80 lbs

**Graphics Controller** 

Quadro™ P5000 graphics

GPU: 2560 NVIDIA® CUDA® Parallel Processing Cores

Power: 180 Watts Cooling: Active

Memory

16GB GDDR5X memory

Memory Bandwidth: Up to 288 GB/s

Memory Width: 256 bit

ECC Memory (disabled by default)

**Connectors** 

DP (x4) with HDR support

DL-DVI(D)

3-pin mini-DIN connector

SLI connector

Quadro Sync connector (compatible with Quadro II Sync)

One 8-pin auxiliary power connector

Factory configured option: No video cable adapter included with card. After market option Kit: No video cable adaptor included with card.

DVI to VGA, DisplayPort™ to VGA, DisplayPort™ to DVI, and DisplayPort™ to Dual-Link DVI adapters available as accessories.

Maximum Resolution 5K support @ 60Hz

1x single-cable 5K monitor, or 2x dual-cable 5K monitors

**Image Quality Features** 

Advanced support for 8-bit, 10-bit, and 12-bit per RGB

color component.

HDCP 2.2 support over DisplayPort™, DVI, and HDMI

connectors

NVIDIA 3D Vision™ and other 3D stereo technologies NVIDIA® Mosaic and nView Desktop Management

Display Outputs1

4x DP1.4 HDR outputs (up to 3840x2160 UHD @ 120Hz refresh, or up

to 8K at 30Hz)



**Technical Specifications - Graphics** 

1x Dual-link DVI-D output (up to 2560 x 1600 @ 60 Hz and

1920x1200 @ 120 Hz)

**GPU Architecture** NVIDIA® Pascal™

**Supported Graphics** 

**APIs** 

DirectX°12, OpenGL° 4.5, OpenCL™ 1.0, Vulkan™ 1.0

Developer API support includes: CUDA C, CUDA C++, DirectCompute

5.0, OpenCL™, Java, Python, and Fortran

**Available Graphics** 

**Drivers** 

Windows® 10 64-bit Windows® 7 64-bit

Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP

support Web site:

http://welcome.hp.com/country/us/en/support.html

Notes 1- Supports up to a total of 4 displays

NVIDIA® Quadro® P6000 1<sup>st</sup> GFX 24GB Graphics **Form Factor** Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 967 grams / 2.14 lbs

**Graphics Controller** NVIDIA® Quadro® P6000 graphics

GPU: 3840 NVIDIA® CUDA® Parallel Processing Cores

Power: 250 Watts Cooling: Active

Memory 24GB GDDR5X memory

Memory Bandwidth: Up to 432 GB/s

Memory Width: 384 bit

ECC Memory (disabled by default)

**Connectors** DP (x4) with HDR support

DL-DVI(I)

3-pin mini-DIN connector

**SLI** connector

Quadro Sync connector (compatible with Quadro II Sync)

One 8-pin auxiliary power connector

Factory configured option: No video cable adapter included with

card.

After market option Kit: No video cable adaptor included with card.

DVI to VGA, DisplayPort<sup>™</sup> to VGA, DisplayPort<sup>™</sup> to DVI, and DisplayPort<sup>™</sup> to Dual-Link DVI adapters available as accessories.



### **Technical Specifications - Graphics**

**Maximum Resolution** 5K support @ 60Hz

1x single-cable 5K monitor, or 2x dual-cable 5K monitors

**Image Quality Features** Advanced support for 8-bit, 10-bit, and 12-bit per RGB

color component.

HDCP 2.2 support over DisplayPort™, DVI, and HDMI

connectors

NVIDIA® 3D Vision™ and other 3D stereo technologies

NVIDIA® Mosaic and nView

**Display Outputs**<sup>1</sup> 4x DP1.4 HDR outputs (up to 3840x2160 UHD @ 120Hz refresh, or

up to 8K at 30Hz)

1x Dual-link DVI-D output (up to 2560 x 1600 @ 60 Hz and

1920x1200 @ 120 Hz)

**GPU Architecture** NVIDIA® Pascal™

**Supported Graphics** 

APIs

DirectX°12, OpenGL° 4.5, OpenCL™ 1.0, Vulkan™ 1.0

Developer API support includes: CUDA C, CUDA C++, DirectCompute

5.0, OpenCL™, Java, Python, and Fortran

**Available Graphics** 

**Drivers** 

Windows® 10 64-bit Windows® 7 64-bit

Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP

support Web site:

http://welcome.hp.com/country/us/en/support.html

**Notes** 1- Supports up to a total of 4 displays

Radeon™ Pro WX 7100 8GB Graphics

Form Factor

Full-Height Single Slot (9.5" Length)

**Graphics Controller** Radeon™ Pro WX 7100 graphics

GPU: 2304 Stream Processors organized into 36 Compute Units

Power: 130 Watts Cooling: Active

Memory 8GB GDDR5 memory

Memory Bandwidth: 7 Gbps / 224 GB/s

Memory Width: 256 bit

**Connectors** 4x DisplayPort™ 1.4 – HDR ready connectors with HBR3 and MST support.

Factory Configured: No video cable adapter included After market option kit: No video cable adapter included

Additional DisplayPort™-to-VGA or DisplayPort™-to-DVI adapters are

available as Factory Configuration or Option Kit accessories.

#### **Technical Specifications - Graphics**

Maximum Resolution 5K support @ 60Hz

1x single-cable 5K monitor, or 2x dual-cable 5K monitors

**Image Quality Features** Advanced support for 8-bit, 10-bit, and 16-bit per RGB color

component. High bandwidth scaler for high quality up and

downscaling

**Display Output** 4 full physical DP1.3 HBR3 / DP1.4 HDR outputs

FreeSync support

**GPU Architecture** GCN 4th Generation

**Supported Graphics APIs** DirectX°12

OpenGL<sup>®</sup> 4.5 OpenCL<sup>™</sup> 2.0 Vulkan<sup>™</sup> 1.0

**Available Graphics** 

**Drivers** 

Windows 10 64-bit Windows® 7 64-bit Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

#### Notes

- HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.
- 8. Radeon VR Ready Creator Products are select Radeon Pro and AMD FirePro™ GPUs that meet or exceed the Oculus Rift or HTC Vive recommended specifications for video cards/GPUs. Other hardware (including CPU) and system requirements recommended by Oculus Rift or HTC Vive should also be met in order to operate the applicable HMDs as intended. As VR technology, HMDs and other VR hardware and software evolve and/or become available, these criteria may change without notice.
- AMD PowerTune and AMD ZeroCore Power are technologies offered by certain FirePro<sup>™</sup> and Radeon<sup>™</sup> Pro products, which are designed to intelligently manage GPU power consumption in response to certain GPU load conditions.
- 10. As of September 2016, certified for DisplayPort™ 1.4 HBR3 and ready for DisplayPort™ 1.4 HDR based on independent verification by DisplayPort™ testing authority. HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.



Technical Specifications – Optical and Removable Storage

#### OPTICAL AND REMOVABLE STORAGE

HP 9.5mm Slim DVD Writer

Description 9.5mm height, tray-load **Mounting Orientation** Either horizontal or vertical

**Interface Type** SATA/ATAPI

Dimensions (WxHxD) 128 x 9.5 x 127mm

Supported Media Types DVD+R

> DVD+RW DVD+R DL DVD-R DL DVD-R **DVD-RW** CD-R CD-RW

CD ROM Read

**Disc Capacity** DVD-ROM 8.5 GB DL or 4.7 GB standard

> Full Stroke DVD < 200 ms (seek) Full Stroke CD < 200 ms (seek)

Maximum Data Transfer

Rates

CD-RW Up to 24X

**DVD ROM Read** DVD+RW Up to 8X

> DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X

CD-ROM, CD-R Up to 24X

Power Source SATA DC power receptacle

> **DC Power Requirements** 5 VDC ± 5%-100 mV ripple p-p

**DC Current** 5 VDC -< 800 mA typical, <1600 mA

maximum

84° F (29° C)

Operating Environmental Temperature 41° to 122° F (5° to 50° C)

(all conditions noncondensing)

**Relative Humidity** Maximum Wet Bulb Temperature 10% to 80%

Operating Systems Supported

Windows 10, Windows 7 Professional 64-bit. Windows Vista Business 64\*, Windows 2000.

Red Hat® Enterprise Linux® (RHEL) WS4\*\*, 5, 6 Desktop/Workstation

SUSE Linux® Enterprise Desktop 10 & 11

\* No driver is required for this device. Native support is provided by the

operating system.

**Kit Contents** HP SATA DVD Writer drive, installation guide.

HP 9.5mm Slim DVD-ROM Description Drive

**Mounting Orientation** 

9.5mm height, tray-load Either horizontal or vertical



### Technical Specifications – Optical and Removable Storage

**Interface Type** SATA / ATAPI Dimensions (WxHxD) 128 x 9.5 x 127mm

**Disc Capacity DVD-ROM** Single layer: Up to 4.7 GB

Double layer: Up to 8.5 GB

**Access Times DVD-ROM Single Layer** < 110 ms (typical)

> CD-ROM Mode 1 < 110 ms (typical) Full Stroke DVD < 230 ms (typical) Full Stroke CD < 220 ms (typical)

Power SATA DC power receptacle Source

> 5 VDC ± 5%-100 mV ripple p-p **DC Power Requirements**

**DC Current** 5 VDC - <800mA typical, < 1600 mA

maximum

10% to 80%

**Operating Environmental** Temperature Relative Humidity

(all conditions noncondensing)

41° to 122° F (5° to 50° C)

Maximum Wet Bulb Temperature 84° F (29° C) Operating Systems Windows 8.1, Windows 7 Professional 64-bit. Windows Vista Business 64\*, Windows 2000.

Red Hat® Enterprise Linux® (RHEL) WS4\*\*, 5, 6 Desktop/Workstation

SUSE Linux® Enterprise Desktop 10 & 11

No driver is required for this device. Native support is provided by the

operating system.

**Kit Contents** 9.5mm Slim DVD-ROM Drive, 5.25" ODD Bay adapter/carrier, slim SATA

data/power cable, installation guide

HP 9.5mm Slim BDXL Blu- Description **Ray Writer** 

Supported

**Mounting Orientation** 

9.5mm height, tray-load Either horizontal or vertical

**Interface Type** SATA/ATAPI

**Dimensions (WxHxD)** 128 x 9.5 x 127mm

Supported Media Types BD-ROM

BD-R BD-RE DVD+R DVD+RW DVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-RW

**Disc Capacity** DVD-ROM 8.5 GB DL or 4.7 GB standard

> Blu-ray 25 GB (single-layer)

50 GB (dual-layer) 100/128 GB (BDXL)

Full Stroke DVD < 230 ms (seek)

### Technical Specifications – Optical and Removable Storage

Full Stroke CD < 220 ms (seek)

< 230 ms (seek) (Full Stroke Blu-ray) Blu-ray

Startup Time (Time to drive ready from tray

loading)

BD-ROM (SL/DL) 25S / 28S BD-R (SL/DL) 255 / 285 BD-RE (SL/DL) 255 / 285 DVD-ROM (SL/DL) 18S / 18S DVD-R (SL/DL) **25S / 25S** 

DVD-RW **25S** DVD+R (SL/DL) 255 / 255

DVD+RW 255 CD-ROM **15S** 

Maximum Data Transfer CD ROM Read

Rates

CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

**DVD ROM Read** DVD+RW Up to 8X

DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X

Blu-ray BD-ROM Up to 6X

BD-ROM DL Up to 6X BD-R Up to 6X BD-R DL Up to 6X BD-R Up to 6X BD-RE SL/DL Up to 6X

SATA DC power receptacle Power Source

> **DC Power Requirements** 5 VDC ± 5%-100 mV ripple p-p 5 VDC -900 mA typical, 2000mA DC Current

> > maximum

**Operating Environmental** Temperature (all conditions non-

condensing)

41° to 122° F (5° to 50° C)

**Relative Humidity** 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)

**Operating Systems** Supported

Windows 8.1, Windows 7 Professional 64-bit, Windows Vista Business 64\*, Windows 2000.

Red Hat® Enterprise Linux® (RHEL) WS4\*\*, 5, 6 Desktop/Workstation

SUSE Linux® Enterprise Desktop 10 & 11

No driver is required for this device. Native support is provided by the

operating system.

**Kit Contents** 9.5mm Slim BDXL Blu-Ray Writer, 5.25" ODD Bay adapter/carrier, slim

SATA data/power cable, installation guide

As Blu-ray is a new format containing new technologies, certain disc. digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-ray titles to play, they may

### Technical Specifications – Optical and Removable Storage

require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this workstation.

HP DX115 Removable Drive Enclosure **Interface Type** Compatible with SAS or SATA controllers. Offers 6Gb/s performance when

used with 6Gb/s HDDs.

**Dimensions** (WxHxD) 147.6mm W x 41.1mm H x 205mm D

(5.81" W x 1.62" H x 8.08" D)

**Approvals** Frame and Carrier: 1.73 kg (3.8 lbs.)

Carrier: 0.45 kg (1 lbs.)

**HP SD Card Reader** 

**Description** Supports hardware ECC (Error Correction Code) function

Supports hardware CRC (Cyclic Redundancy Check) function

Supports SD 4-bit parallel transfer mode

Interface Type

**Dimensions** (WxHxD)

USB 3.0 High-speed interface

1.15 x .9 x .15 in (29.00 x 23.6 x 3.15 mm) Fits conveniently in the Front IO

Bay

**Supported Media Types** Secure Digital Card (SD)

Secure Digital High Capacity (SDHC) SD Extended Capacity Memory Card (SDXC)

SD Ultra High Speed II(SD UHSII)

These additional media types are supported with a card adapter.

Memory Stick Micro (M2)

miniSD

miniSD High Capacity

Micro SD Memory Card (MicroSD)

Micro SD High Capacity Memory Card (MicroSDHC)

Test Parameters/Conditions - Power applied, unit operating on system

±5%

Operating Systems Supported Windows 10

No driver is required for this device. Native support is provided by the

operating system.

**Kit Contents** Media card reader

**Approvals** USB-IF, WHQL, Compliant with USB Mass Storage Class Bulk only Transport

Specification Rev. 1.0.

Compliant Intel® Front Panel I/O Connectivity Design Guide V. 1.3, FCC, CE,

BSMI, C-Tick, VCCI, MIC, cUL, TUVT

**Weight** 0.35 lbs. (0.16 kg)

### Technical Specifications - Controller Cards

#### **CONTROLLER CARDS**

HP Thunderbolt-3 Dual Port2 PCIe 1-port I/O Card Data Transfer Rate
Devices Supported

Supports up to 40 Gb/s (40,000 Mb/s)

Thunderbolt™, Thunderbolt™ 2 and Thunderbolt™ 3 certified for Windows

devices

**Bus Type** PCIe card, full height PCIe slots

Ports Two Thunderbolt™ 3 external USB type-C output connectors (Rear)

Two full size DisplayPort input connectors (Rear)

**Internal Connectors** One 2x5-Pin header connector

System Requirements Genuine Windows 10 Professional 64-bit, available dedicated PCH PCIe

slot.

**Temperature - Operating** 50° to 131° F (10° to 55° C) **Temperature - Storage** -22° to 140° F (-30° to 60° C)

Relative Humidity -

Operating

20% to 80%

**Compliances** FCC Part 15B, cULus 60950, CE Mark EN55022B(1995)/EN55024-1998 STD,

Taiwan BSMI CNS13438, Korea MIC

**Operating Systems** 

Supported

Genuine Windows 10 Professional 64-bit.

**Kit Contents** HP Thunderbolt™ 3 Dual Port PCIe I/O Card, 2- DisplayPort cables, GPIO

(General-Purpose Input/Output) cables, Installation documentation and

warranty card.



<sup>\*</sup>Maximum speed requires DisplayPort™ and PCIe aggregation.

Technical Specifications - Networking and Communications

#### **NETWORKING AND COMMUNICATIONS**

Integrated Intel® I219LM Connector **RJ-45** 

> Intel® I219LM Controller **Data Rates Supported** 10/100/1000 Mbps

**Boot ROM Support** PXE, UEFI

**Connect Speed LED** 

**Indicators** 

Link/Activity LED

Off = No link

Blinking = Activity

Speed LED

Off = 10Mbps

Amber = 100Mbps

Green = 1000Mbps

Management Capabilities Intel® Active Management Technology™ 11

Integrated Intel® X722 for 1GbE

Connector 1 RJ-45

Controller Intel® X722 for 1GbE

**Data Rates Supported** 1000 Mbps **Boot ROM Support** PXE, UEFI

**Connect Speed LED** Indicators

Off = No link

Blinking = Activity

Speed LED

Link/Activity LED

Off = No Link

Green = 1000Mbps

Cabled from Dedicated Rear I/O Slot

Management Capabilities Wake-On-LAN

**HP Z Dual 10GbE Network Networking Interface** 

Module

2 RJ-45

**System Interface Networking Speeds** 

Supported

1Gbps, 10Gbps

Cabling (up to 100m)

Cat5e (or higher) for 1Gbps

Cat6a (or higher) for 10Gbps

**Power Consumption** (active-typical)

5.5W at 1Gbps 11.2W at 10Gbps

**Physical Dimensions** 

0.875 in x 3 in x 2.75 in

**Connect Speed LED** 

Link/Activity LED

**Indicators** 

Off = No link

Blinking = Activity

Speed LED

Amber = 1Gbps

Green = 10Gbps

0 °C to 55 °C (32 °F to 131 °F) **Operating Temperature** 

Intel® I210-T1 **Networking Interface** 1 RJ-45



### Technical Specifications - Networking and Communications

System Interface

**Networking Speeds** 

Supported

10Mbps, 100Mbps, 1Gbps

PCI Express 2.1 x1

Cabling (up to 100m) Cat3 (or higher) for 10Mbps

Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps

Power Consumption (active-typical)

0.81W

Physical Dimensions

Length: 6.7cm (2.64 inches)

(Bracket) Width: 1.8cm (0.709 inches)

Full-height end bracket: 12.07cm (4.755 inches) Low-profile end bracket: 8cm (3.15 inches)

Connect Speed LED Indicators

Link/Activity LED

Off = No link

• Blinking = Activity

Speed LED

Off = 10Mbps

Green = 100Mbps

Amber = 1Gbps

Operating Temperature

0 °C to 55 °C (32 °F to 131 °F)

**Hardware Certifications** 

USA: FCC B, EU: UL CE, Japan: VCCI,

Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC,

Canada: ICES-003/NMB-003

Intel® 1350-T2

**Networking Interface** 

2 RJ-45

**System Interface** PCI Express 2.1 x4

Networking Speeds Supported

10Mbps, 100Mbps, 1Gbps

Cabling (up to 100m)

Cat3 (or higher) for 10Mbps Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps

Power Consumption (active-typical)

4.4W

**Physical Dimensions** 

Length: 13.54cm (5.33 inches)

Width: 6.89 (2.71 inches)

Full-height end bracket: 12.0cm (4.725 inches) Low-profile end bracket: 7.92cm (3.117 inches)

Connect Speed LED Indicators

Link/Activity LED

• Off = No link

Blinking = Activity

Speed LED

Off = 10Mbps

Green = 100Mbps

Amber = 1Gbps

**Operating Temperature** 0 °C to

0 °C to 55 °C (32 °F to 131 °F)



### Technical Specifications - Networking and Communications

**Hardware Certifications** USA: FCC B.

> EU: UL CE. Japan: VCCI, Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC,

Canada: ICES-003/NMB-003

Intel® 1350-T4 **Networking Interface** 4 RJ-45

> System Interface PCI Express 2.1 x4

**Networking Speeds** 

Supported

10Mbps, 100Mbps, 1Gbps

Cabling (up to 100m) Cat3 (or higher) for 10Mbps

> Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps

**Power Consumption** (active-typical)

**Physical Dimensions** 

Length: 13.54cm (5.33 inches)

Width: 6.89 (2.71 inches)

Full-height end bracket: 12.0cm (4.725 inches) Low-profile end bracket: 7.92cm (3.117 inches)

**Connect Speed LED Indicators** 

Link/Activity LED

Off = No link

Blinking = Activity

Speed LED

Off = 10Mbps

Green = 100Mbps

Amber = 1Gbps

**Operating Temperature** 

**Hardware Certifications** 

0 °C to 55 °C (32 °F to 131 °F)

USA: FCC B, EU: UL CE, Japan: VCCI.

Taiwan: BSMI.

Australia/New Zealand: CTICK,

Korea: KCC.

Canada: ICES-003/NMB-003

Aguantia® AQN-108 **Networking Interface RJ-45** 

**System Interface** PCI Express 3 x1

**Networking Speeds** 

Supported

100Mbps, 1Gbps, 2.5Gbps, 5Gbps

Cabling (up to 100m) **Power Consumption** 

(active-typical)

Cat5e (or higher) for all speeds 3.5W at 5Gbps, 3.0W at 2.5Gbps

**Physical Dimensions** 

3.72 in x 3.18 in (without bracket)

#### Technical Specifications - Networking and Communications

**Connect Speed LED** Indicators

Link/Activity LED

Off = No link

Blinking = Activity

Speed LED

Off = No link

Amber = <5Gbps

Green = 5Gbps

0 °C to 55 °C (32 °F to 131 °F)

**Operating Temperature** 

**Hardware Certifications** USA: FCC B.

EU: UL CE.

Japan: VCCI, Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC,

Canada: ICES-003/NMB-003

Intel® X550-T2

**Networking Interface** 

**System Interface** 

**Networking Speeds** 

Supported

Cabling (up to 100m)

2 x RJ-45

PCI Express 3 x4

100Mbps, 1Gbps, 2.5Gbps, 5Gbps, 10Gbps

Cat5 (or higher) for 100Mbps

Cat5e (or higher) for 1Gbps, 2.5Gbps, or 5Gbps

Cat6a (or higher) for 10Gbps

**Power Consumption** (active-typical)

3.9W at 100Mbps 5.5W at 1Gbps 11.2W at 10Gbps

**Physical Dimensions** 

**Connect Speed LED** 

**Indicators** 

Link/Activity LED

Off = No link

Blinking = Activity

5.2 in x 2.7 in (without bracket)

Speed LED

Off = No link

Amber = <10Gbps

Green = 10Gbps

**Operating Temperature** 

0 °C to 55 °C (32 °F to 131 °F)

**Hardware Certifications** 

USA: FCC B. EU: UL CE, Japan: VCCI, Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC.

Canada: ICES-003/NMB-003

Intel® X710-DA2 10GBASE-SR Converged **Network Adapter** 

**Networking Interface** System Interface **Networking Speeds** 

Supported

2 SFP+ Ports for LC SFP+ Transceivers

PCI Express 3.0 x8 1Gbps, 10Gbps



### Technical Specifications - Networking and Communications

Cabling LC fiber optic cabling with LC SFP+ Transceivers

Power Consumption (active-typical)

4.3W

Physical Dimensions 6.578 in x 2.703 in
Connect Speed LED Link/Activity LED
Indicators • Off = No Ii

Off = No linkBlinking = Activity

Speed LED

Off = 10MbpsGreen = 100MbpsAmber = 1Gbps

**Operating Temperature**  $0 \, ^{\circ}\text{C}$  to 55  $^{\circ}\text{C}$  (32  $^{\circ}\text{F}$  to 131  $^{\circ}\text{F}$ )

Hardware Certifications USA: FCC B, EU: UL CE, Japan: VCCI,

Japan: VCCI, Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC,

Canada: ICES-003/NMB-003

**Note:** Windows 7 is NOT supported

10GbE SFP+ SR Conn Transceiver Cable

**Connector Type** LC

Cable Type 62.5/125um or 50/125um (core/cladding), graded-index, low metal

content, multimode fiber optic, complying with ITU-T G.651 and ISO/IEC

793-2 Type A1b or A1a, respectively.

Cable Length2-300mWavelength850nmForm FactorSFP+

**Physical Dimensions**  $0.47(h) \times 0.54(w) \times 2.19(d)$  inches

(1.19 x 1.38 x 5.57 cm)

**Operating Temperature** OC to 45C (32F to 113F) **Operating Humidity** 0% to 85%, noncondensing

Intel® 8265 WLAN Networking Speeds 802.11ac MU-MIMO (up to 867 Mbps)

Bluetooth 4.2

**IEEE WLAN Standard** IEEE 802.11a/b/g/n/ac, 802.11d, 802.11e, 802.11h, 802.11i, 802.11w;

802.11r, 802.11k, 802.11v pending

Bluetooth 4.2

System Interface PCI Express 2.1 x1

Antenna 2x2

### **Summary of Changes**

### **SUMMARY OF CHANGES**

Date of change:	Version History:		Description of change:
November 1, 2017	From v1 to v2	Added	HP DisplayPort to HDMI Adapter, HP DisplayPort to VGA Adapter, NVIDIA SLI 3-slot Graphics Connector and NVIDIA Quadro Sync II to Graphics section and Microsemi 3152-8i SAS ROC RAID Controller
		Changed	Graphics, Storage / Hard Drives and Memory sections, changed Front and internal view info on the Overview section, changed Operating Systems section, changed System Board section, Physical Security and Serviceability sections
November 29, 2017	From v2 to v3	Added	Processors, hard drives and graphics to offerings, added Declared Noise Emissions information
January 30, 2018	From v3 to v4	Removed	NVIDIA SLI Graphics Connectors from Graphics Cable Adapters section
March 27, 2018	From v4 to v5	Added	Intel Xeon processors added
April 16, 2018	From v5 to v6	Removed	RAID 5
August 13, 2018	From v6 to v7	Added	Footnote to Networking and Communications section
		Changed	Processors section and Operating Systems section
September 4, 2018	From v7 to v8	Removed	HP IEEE 1394b FireWire PCIe Card
September 6, 2018	From v8 to v9	Removed	Microsemi 3152-8i SAS ROC RAID Controller
September 21, 2018	From v9 to v10	Added	Intel Optane SSD 905p AiC 280GB & 480GB



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